

# Multi Fractal SEMICONDUCTORS



Unlocking the mmWave spectrum and enabling the 4th IR  
– 5G - from small cells to massive MIMO and the IoT

# AGENDA

Let's begin!



**IEEE**  
**ComSoc**<sup>TM</sup>  
IEEE Communications Society



**IEEE**  
**Future**  
**NETWORKS**<sup>TM</sup>  
Enabling 5G and Beyond



UNIVERSITEIT VAN PRETORIA  
UNIVERSITY OF PRETORIA  
YUNIBESITHI YA PRETORIA

**Faculty of Engineering,  
Built Environment and  
Information Technology**  
Fakulteit Ingenieurswese, Bou-omgewing en  
Inligtingtegnologie / Lefapha la Boetšenere,  
Tikologo ya Kago le Theknolotši ya Tshedimošo

-  **Welcome**  
Glad to be here!
-  **Introduction**  
What is 5G really? New apps only?  
What are the key enabling techs?
-  **Market opportunity**  
What is the problem? Our niche.
-  **Our value proposition**  
How we will make E-band a *coverage* spectrum.
-  **Business strategy**  
What we've done and where we're going.
-  **Q&A**  
Want to know more?

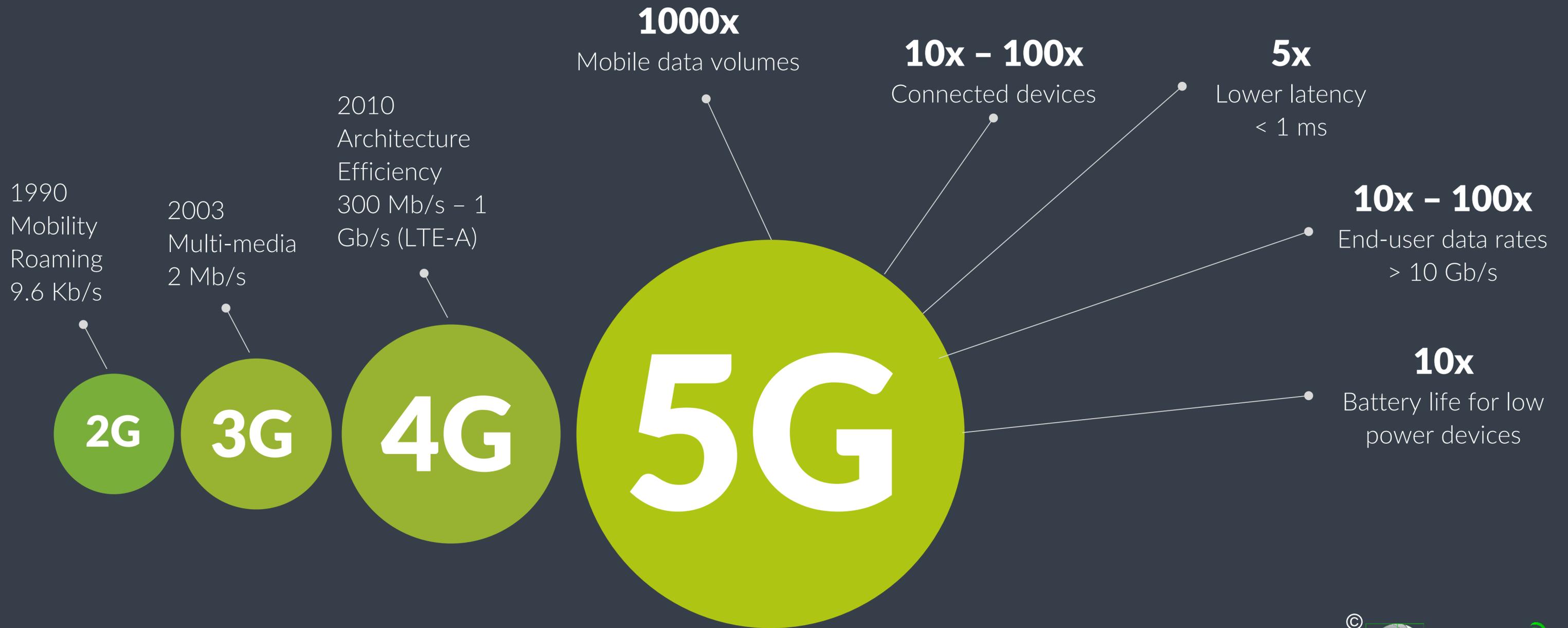
A futuristic cityscape at night, viewed from a high angle. The city is illuminated with various lights, and a network of glowing blue lines connects various points across the city, suggesting a 5G network. In the center, the letters '5G' are displayed in a large, glowing, neon-like font. The city is set against a dark blue sky with stars and a few clouds. The city is built on a dark, rocky surface that appears to be floating in space.

# INTRODUCTION

What is 5G really? New apps only? What are the key enabling techs?

# INTRODUCTION

Evolution of 5G



Source: METIS

# INTRODUCTION

Network as a service – SDN/NFV



Network Slicing

10 Gb/s

**eMBB**

Enhanced Mobile  
Broadband

3D video, VR, UHD

Work & play in the cloud

Augmented reality

Industry automation

Mission critical apps

Self driving cars

< 1ms

**uRLLC**

Ultra-reliable and Low-  
latency Communications

Service-driven  
architecture

- Multiple services, standards & site types
- Multi-connectivity technologies (LTE, WiFi, Fibre)
- On-demand deployment (re-configurability)
- Flexible and fast orchestration of eMBB, uRLLC, mMTC

Smart buildings

Smart-cities

1 million / km<sup>2</sup>

**mMTC**

Massive Machine Type  
Communications

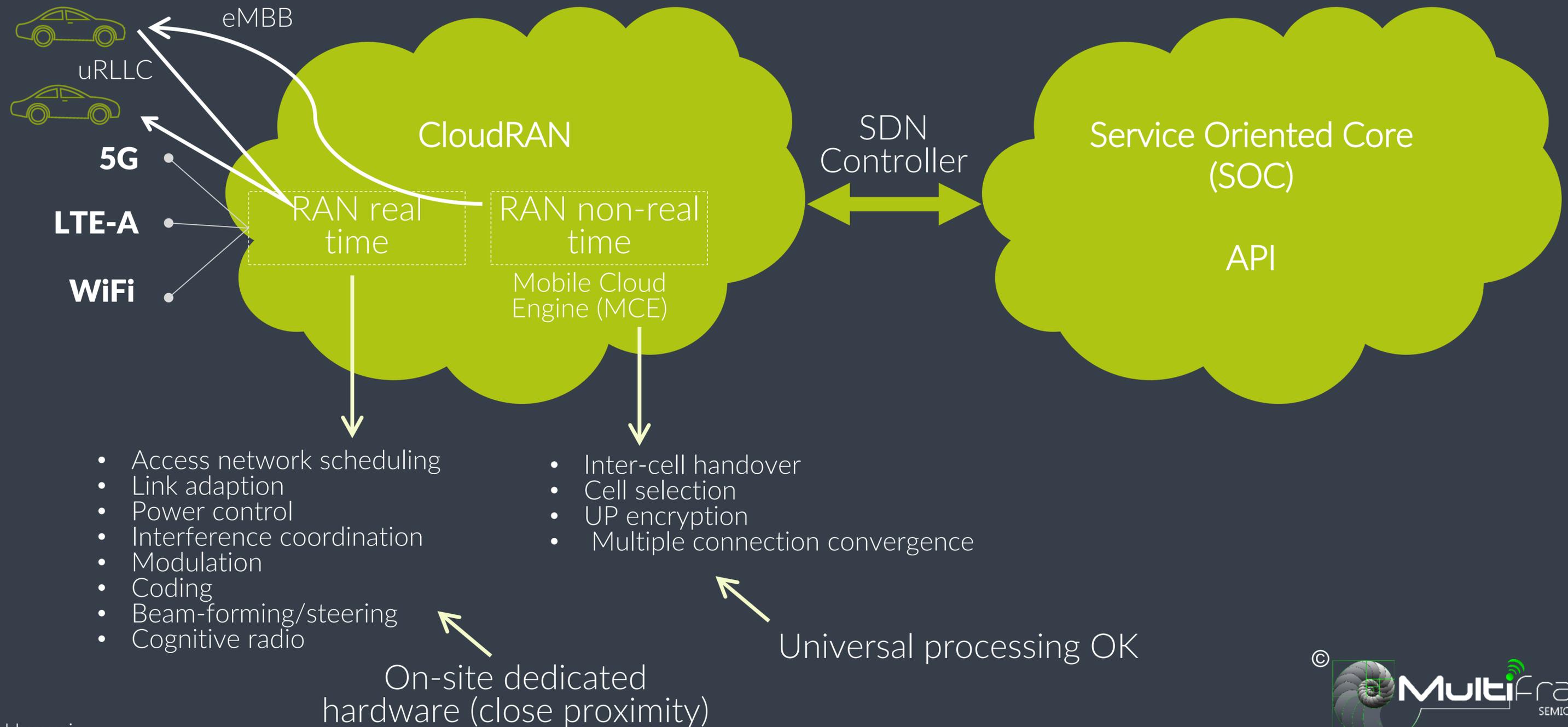
Source: Nokia



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# INTRODUCTION

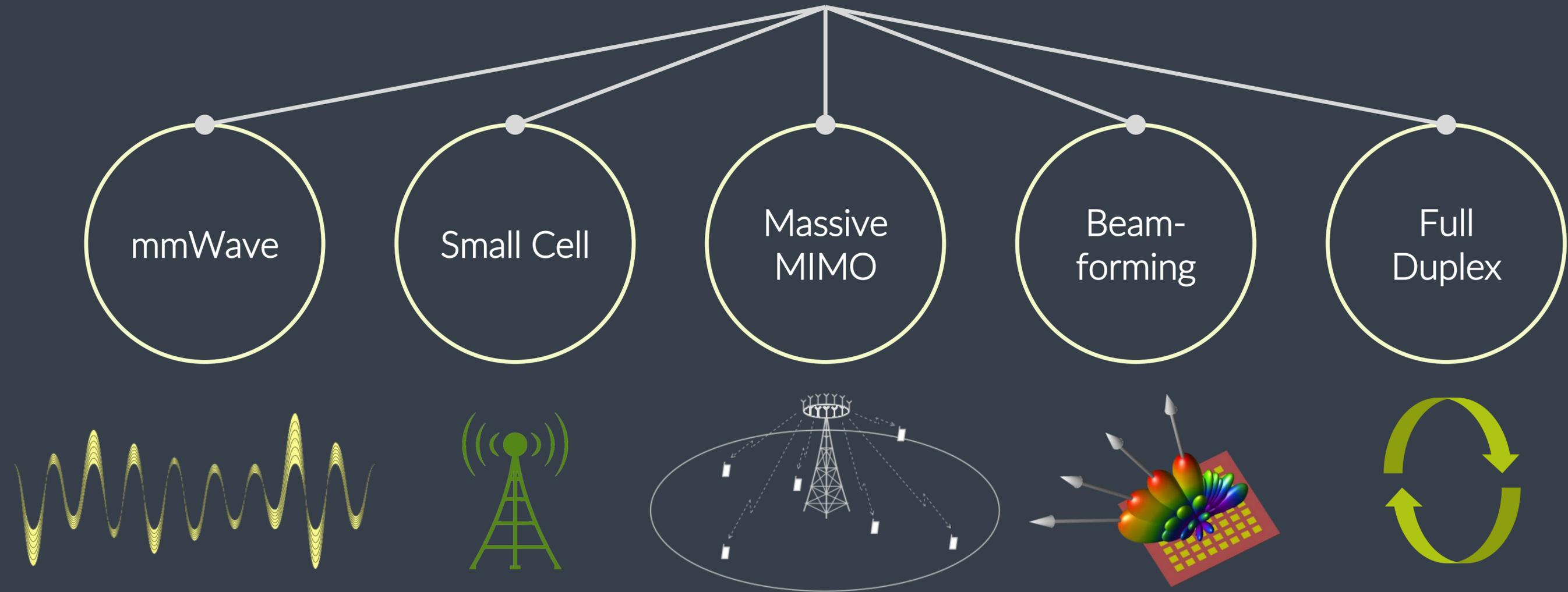
Network as a service – SDN/NFV



# INTRODUCTION

Key enabling 5G technologies

## 5G

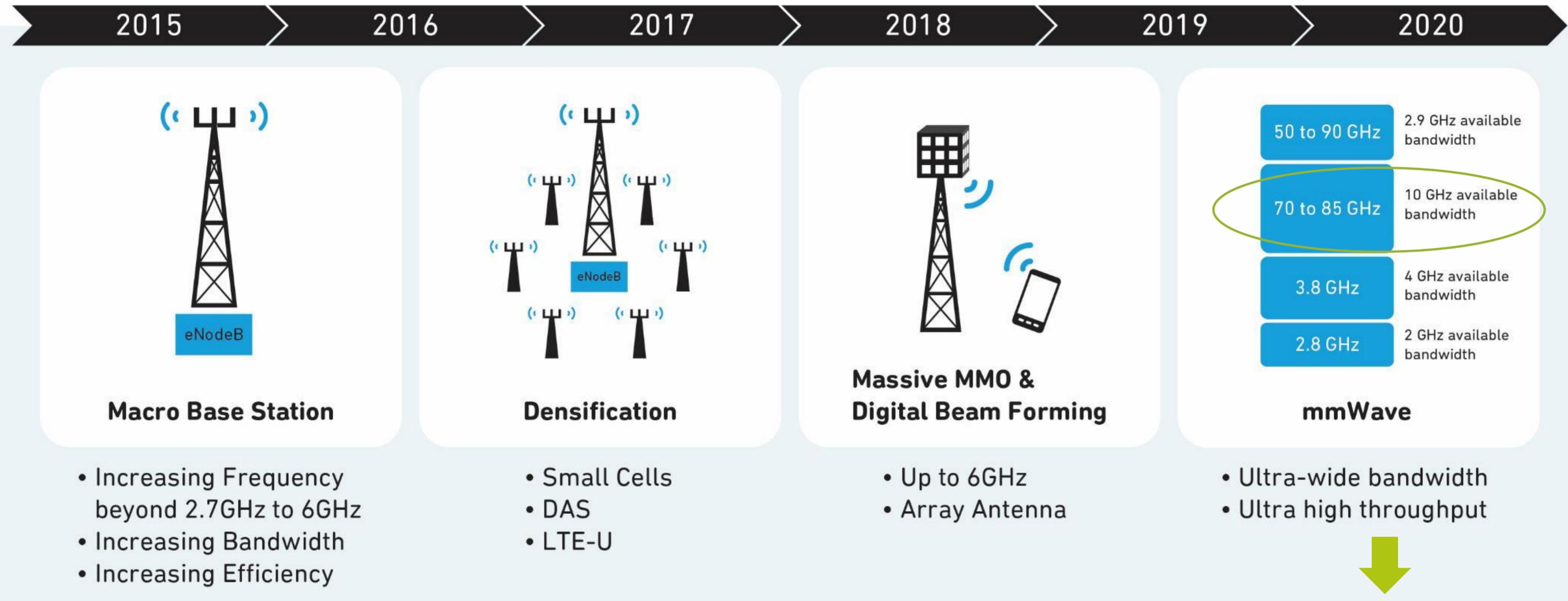


# MARKET OPPORTUNITY

What is the problem? Our niche.



## The Evolution of 5G

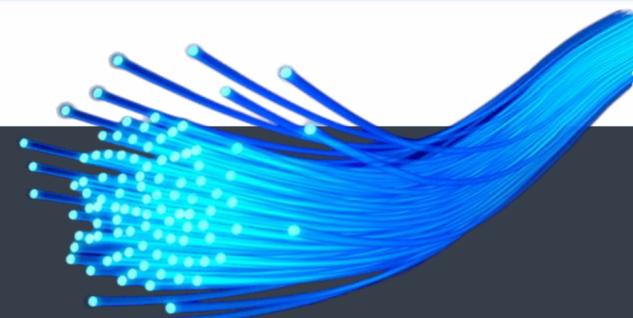


Source: Qorvo

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QORVO

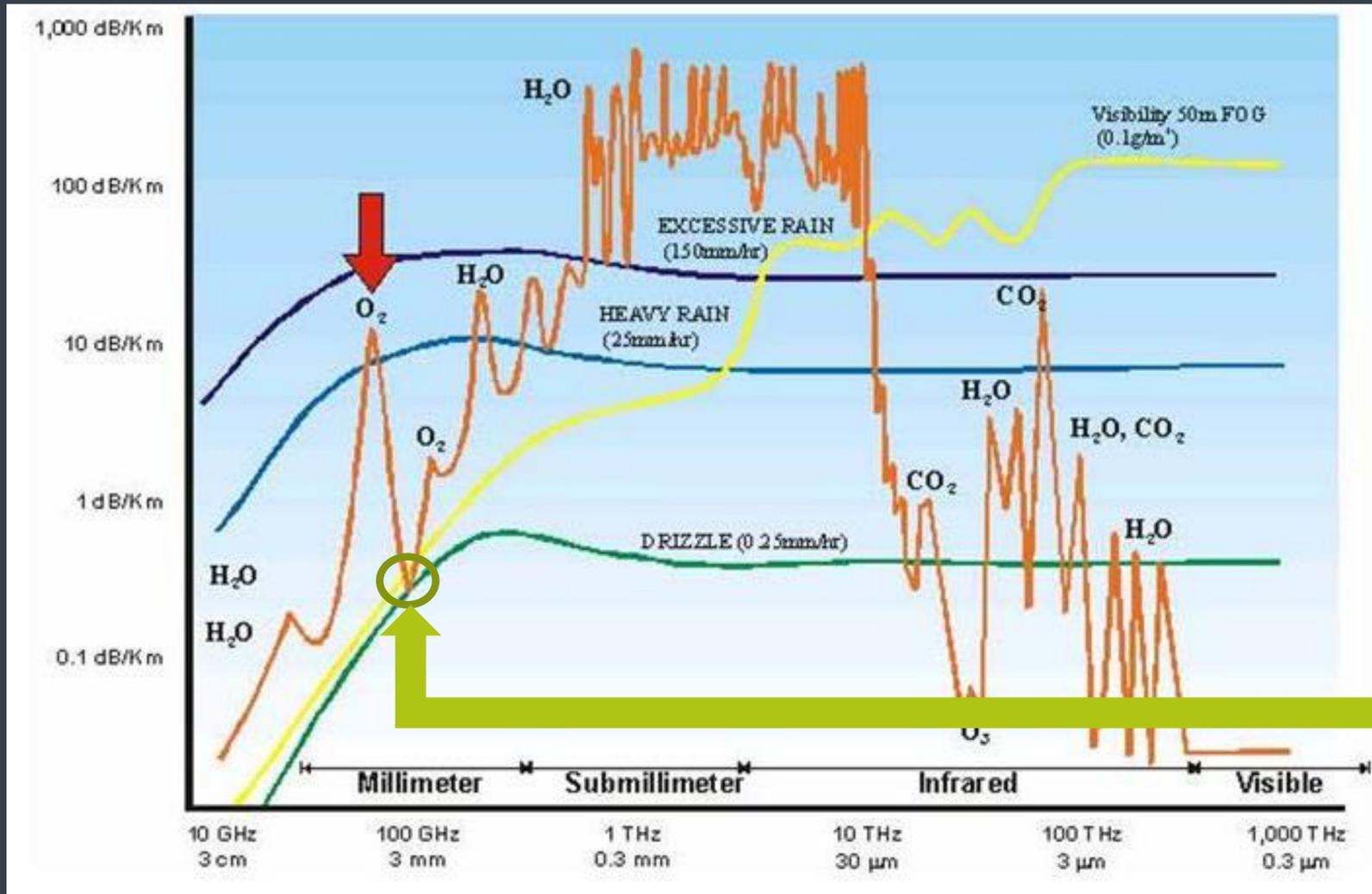
Fibre in the air!



# E-BAND - THE NEXT FRONTIER (70-120 GHz)

Why focus on E-band?

Atmospheric attenuation



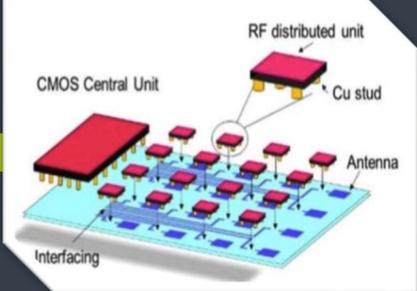
E-band



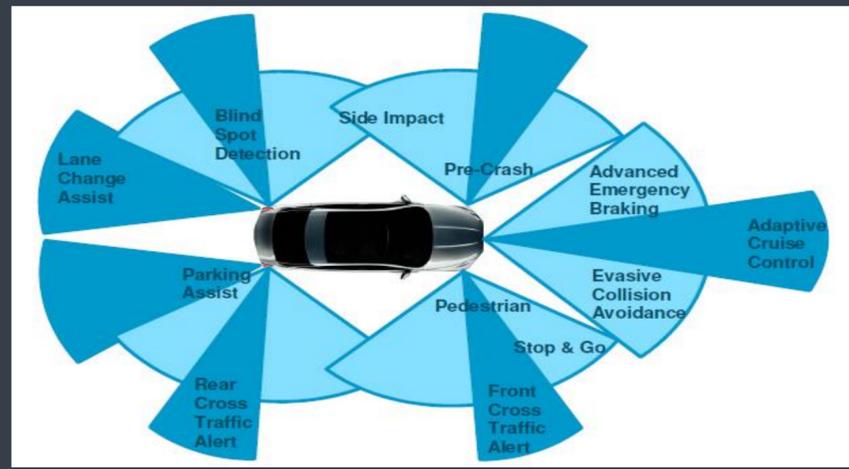
Gold mine! This opportunity will never appear in the radio spectrum ever again! Ever.

# APPLICATIONS AND OUTLOOK

64x64 > 4000 ICs



MMIMO



Automotive RADAR

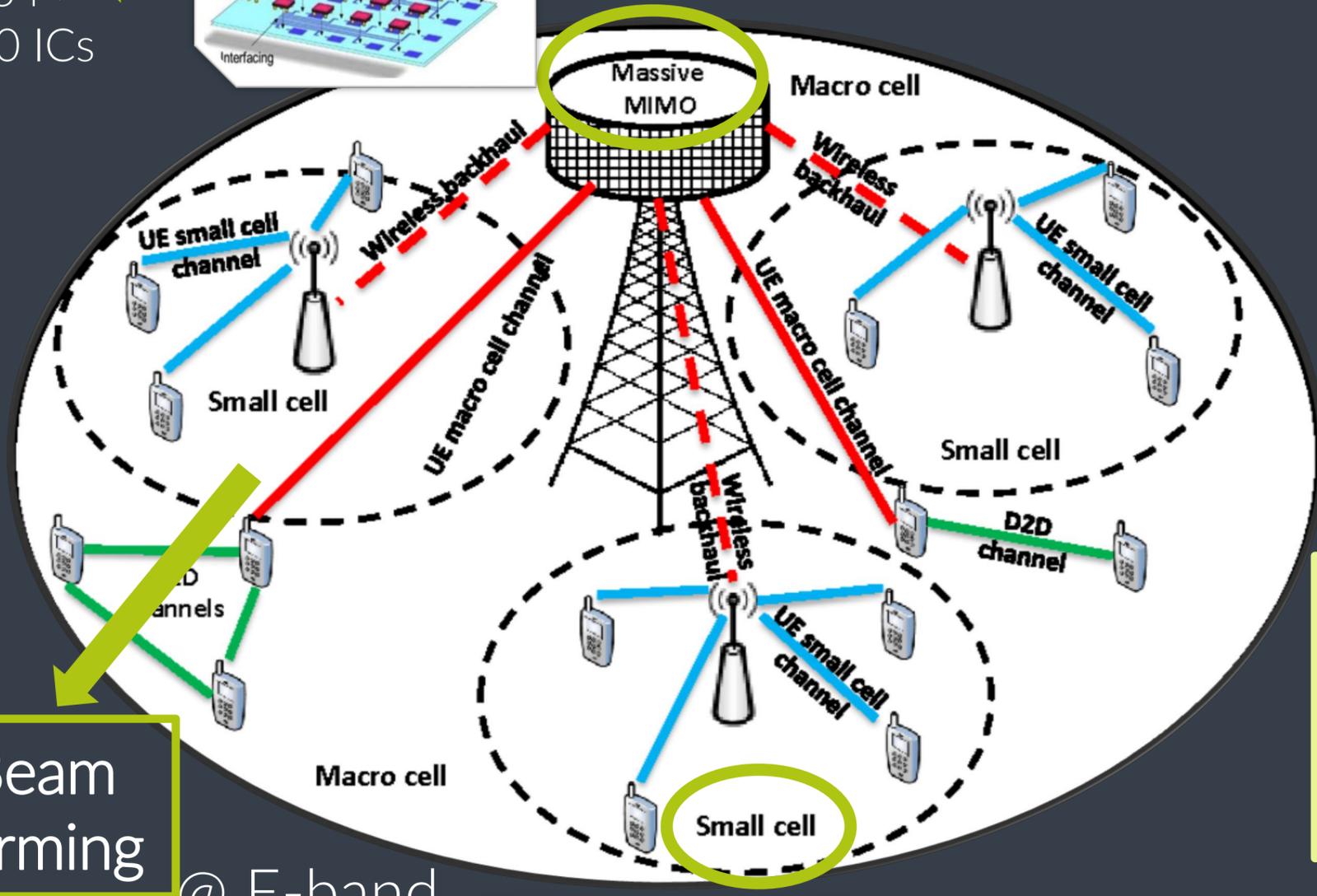
1. 5G Backhaul
  2. 5G Fronthaul
  3. Fixed wireless access
  4. 5G Mobile access
  5. Sat to surface
  6. Automotive radar
- We believe the world will be blanketed by E-band by 2025*

- Gaps in market:
- No E-band filters on-chip
  - DSP – big data problem

Beam forming

@ E-band

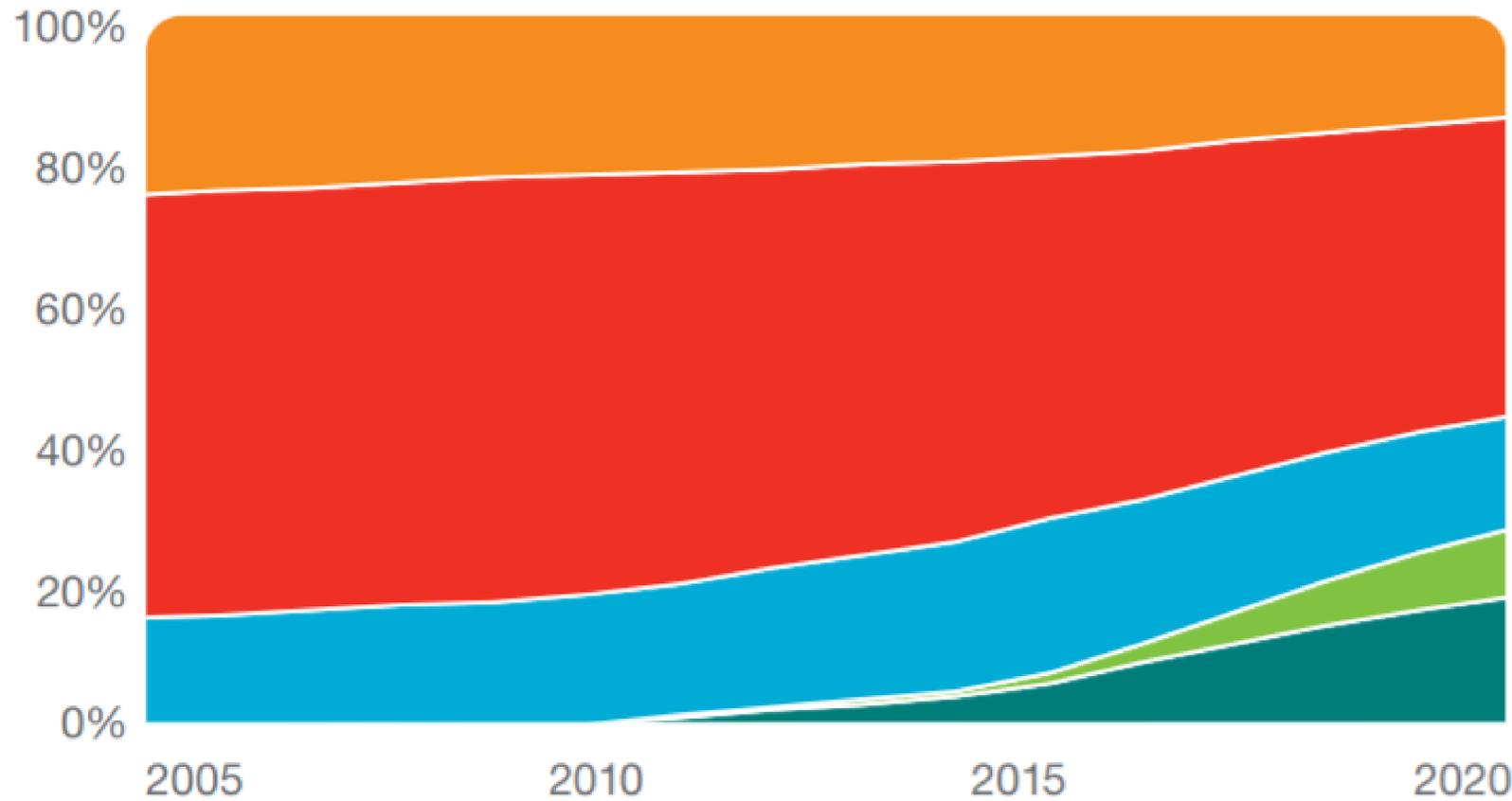
Small Cells



# MAJOR INDUSTRY PLAYERS THINK SO TOO

Figure 10: New deployment share per frequency range [GHz]

6-13    15-23    26-42    60    70/80



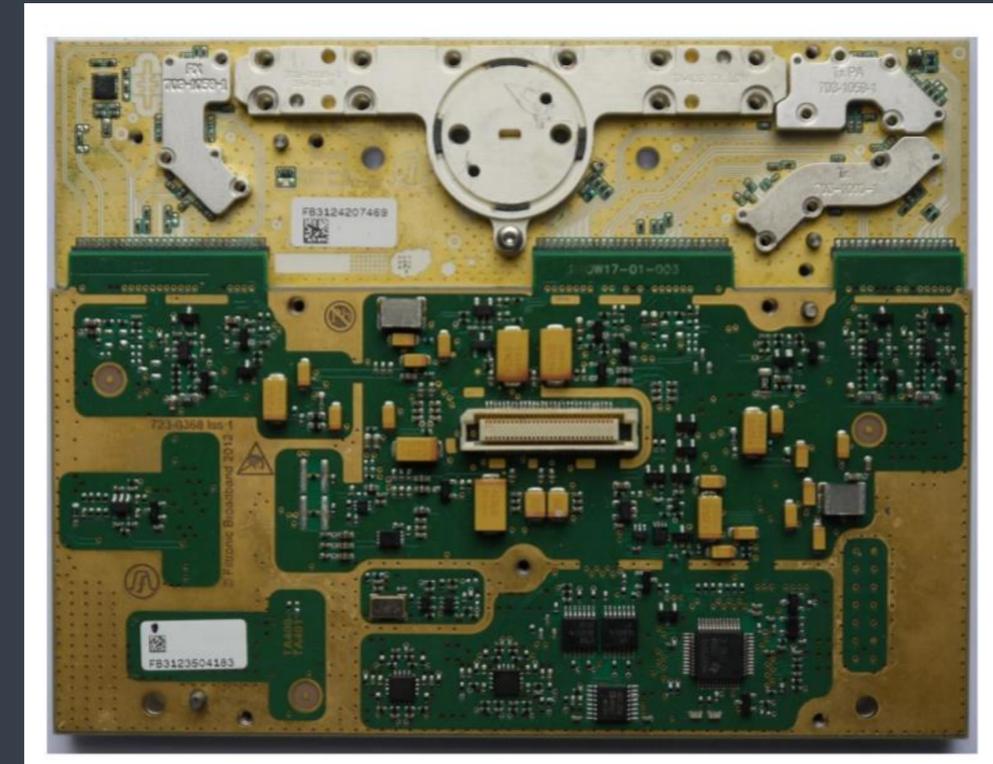
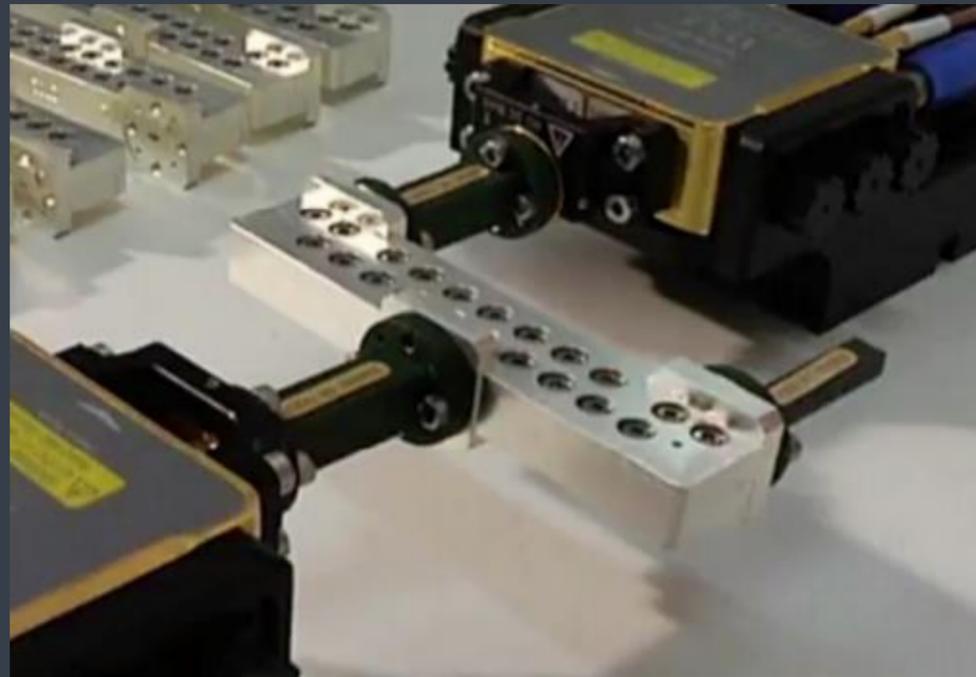
Traditional bands still represent 70% of new deployments in 2020

Major growth in E-band – up to 20% in 2020



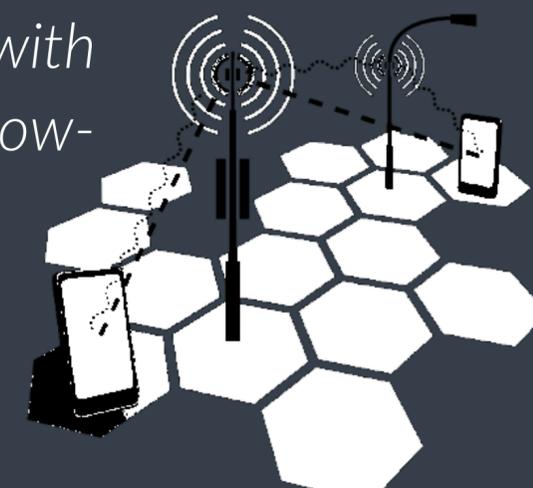
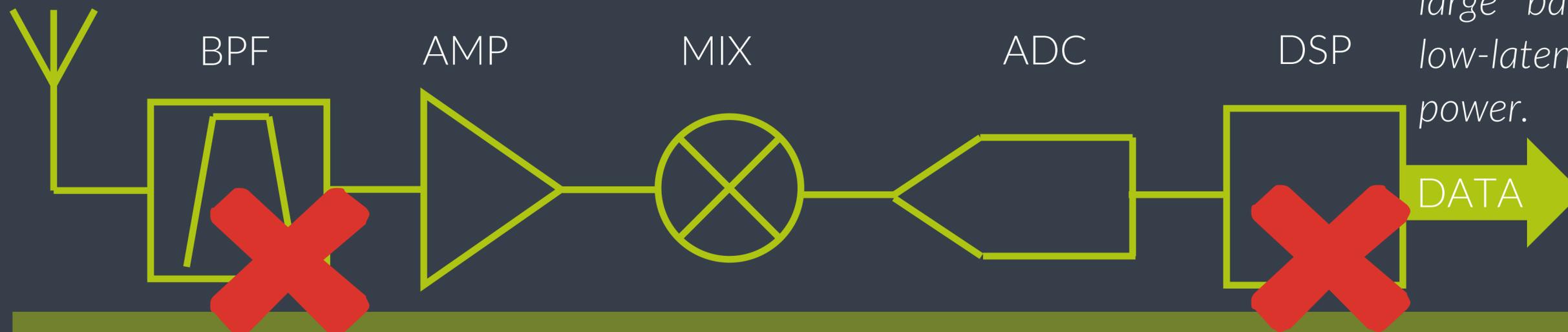
Source: Ericsson (2015)

# SO WHAT IS THE PROBLEM? BULKY FRONT ENDS



Problem 1: Lack of on-chip mmWave BPFs.

Problem 2: Processing large bandwidths with low-latency and low-power.



Challenges: size, cost and power consumption. Unfit for small cell/MIMO.

# BULKY FRONT ENDS

## Wavence

[networks.nokia.com/products/wavence](https://networks.nokia.com/products/wavence)

## Mini-Link

<https://www.ericsson.com/en/portfolio/networks/ericsson-radio-system/mobile-transport/microwave/all-outdoor-shorthaul>

## RTN-380

<http://carrier.huawei.com/en/products/wireless-network/microwave/e-band>

## GX4000

<https://www.fujitsu.com/us/Images/GX4000-ds.pdf>

## iPASOLINK EX

[https://www.nec.com/en/global/prod/nw/pasolink/products/ipasolinkEX\\_solution01.html](https://www.nec.com/en/global/prod/nw/pasolink/products/ipasolinkEX_solution01.html)

## EtherHaul

<https://www.siklu.com/product/etherhaul-kilo-series/>



Nokia Networks



ERICSSON



HUAWEI



FUJITSU



NEC



Siklu



DragonWave, E-band communications, Ceragon, Intracom, Airspan, Cablefree, Siae Microelectronica, Lightpointe



# BULKY FRONT END PROBLEM

## SMALL CELLS

No viable solutions at E-band for true Small Cell densification

Existing solutions: E-band

- \$11k per link
- > 1m<sup>2</sup> real-estate
- ~ kW of power

1. Small Cell

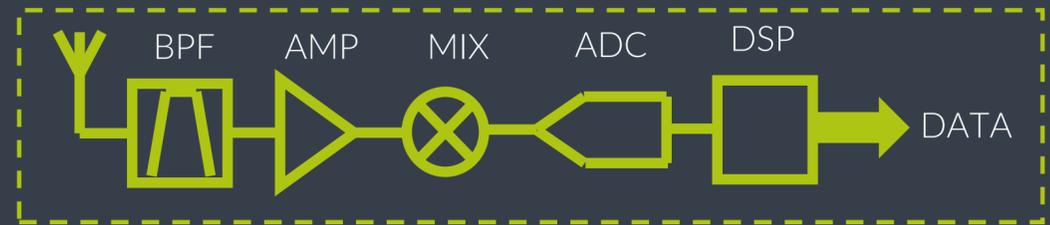


X1 Every 50m<sup>2</sup> = Many MILLIONS

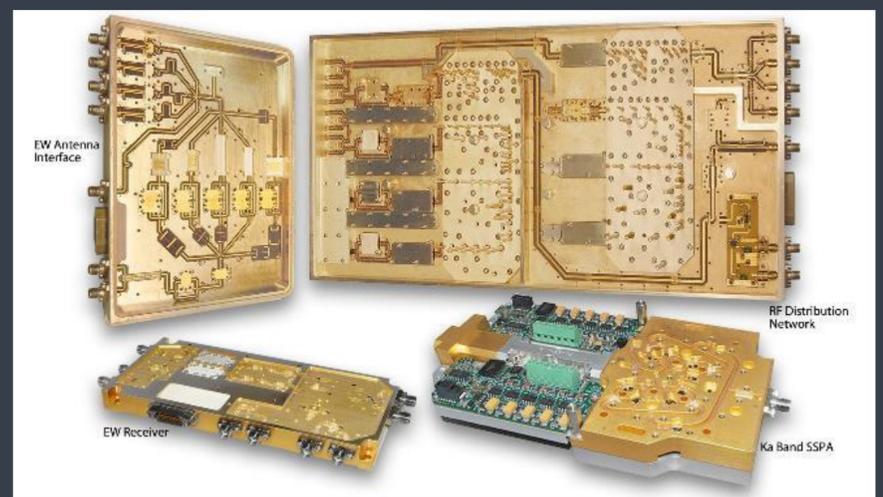
- \$ Many Billions
- Millions m<sup>2</sup> real-estate
- ~ MWs of power

\$\$\$\$\$\$\$\$

impossible



Integrated Microwave Assembly (IMA) → \$\$\$\$



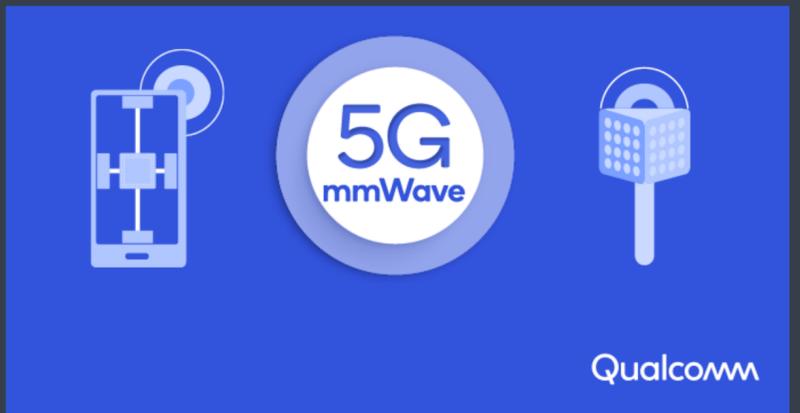
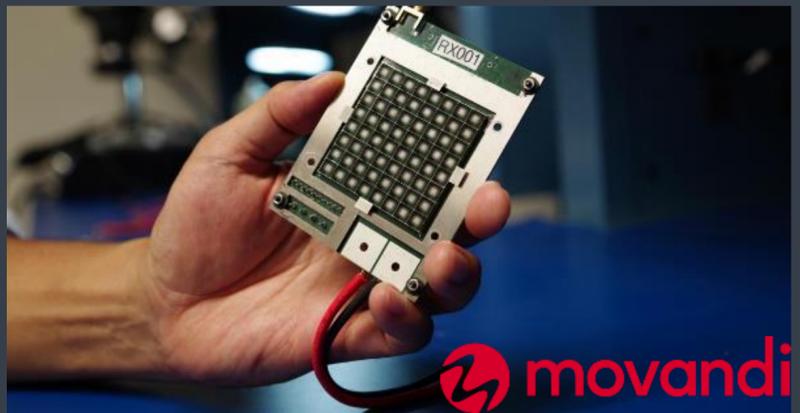
# BULKY FRONT END PROBLEM

MMIMO

Existing solutions: 28 GHz, 39 GHz

No solutions at E-band

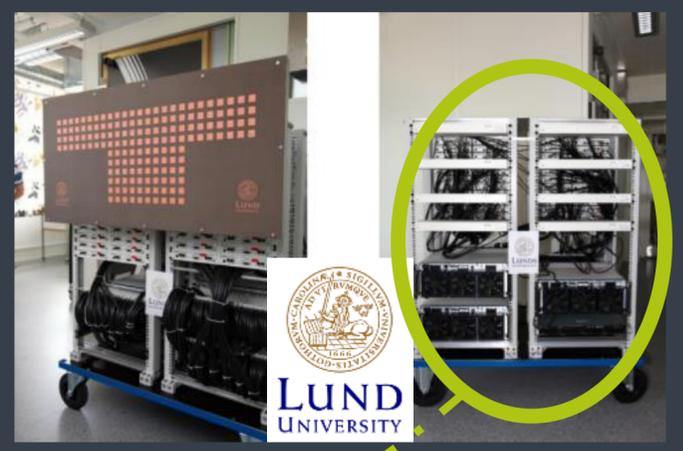
2. MMIMO



A solution like this is needed!

vs.

Existing solutions: < 6GHz

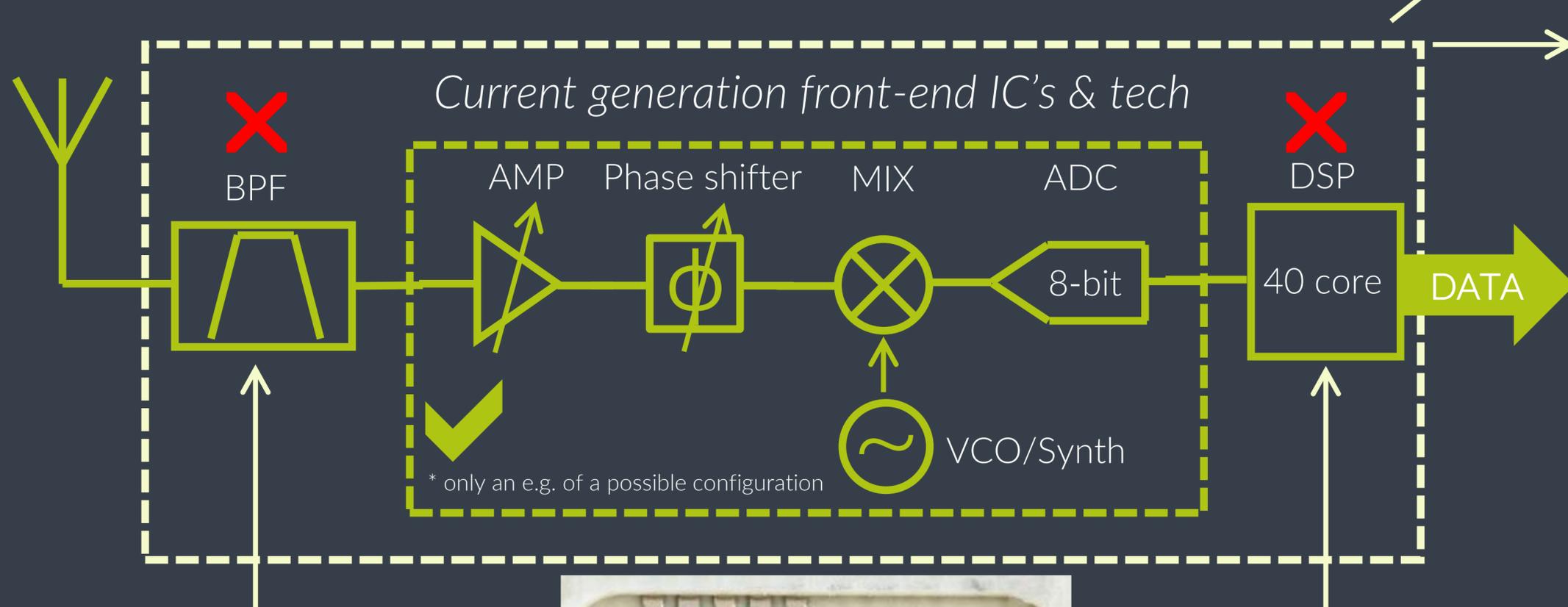


Real-estate? Power? \$\$\$\$?

Bulky, expensive, power hungry  
→ No-go

# SUMMARY OF EXISTING SOLUTIONS

Size of a shoe-box

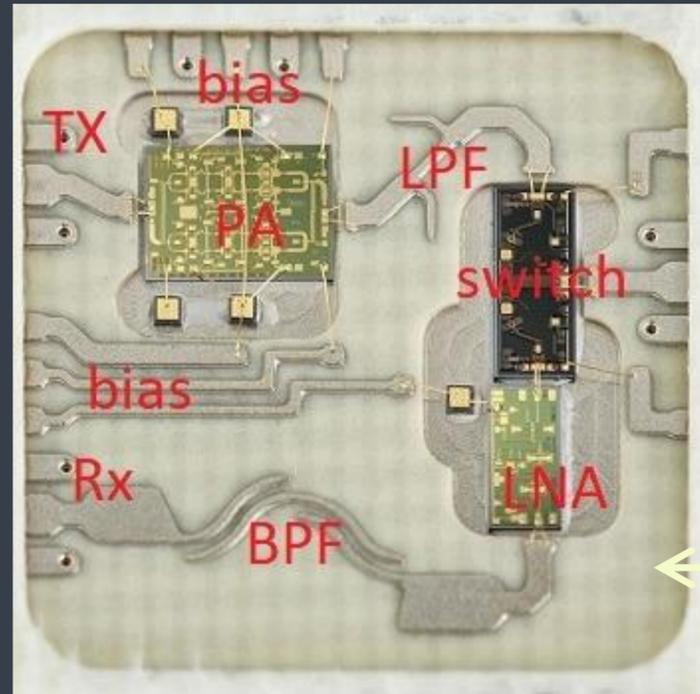


IMA (Integrated Microwave Assembly)

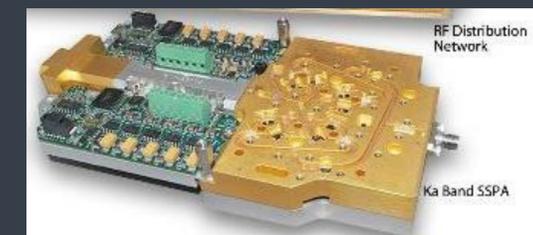
- Thousands of \$
- Manufacturing difficulty
- Low volume
- Power hungry
- Big and bulky



SAW, BAW, waveguide (off-chip) – integration problem



Big-data problem



IMA

“mmWave will never materially scale beyond small pockets of 5G hotspots in dense urban environments”

-- T-Mobile CTO Neville Ray

“We will need to remind ourselves, this is not a coverage spectrum”

-- Verizon CEO Hans Vestberg

“The roll-out of 5G in the country will be much more case-based”

-- MTN South Africa CEO Rob Shuter

Millimeter-wave 5G isn't for widespread coverage, Verizon & T-Mobile admit

# NO SMALL CELL OR MMIMO E-BAND SOLUTION IN SIGHT FOR MAJOR INDUSTRY PLAYERS!



## Built on 5G Challenge

## What we're looking for.

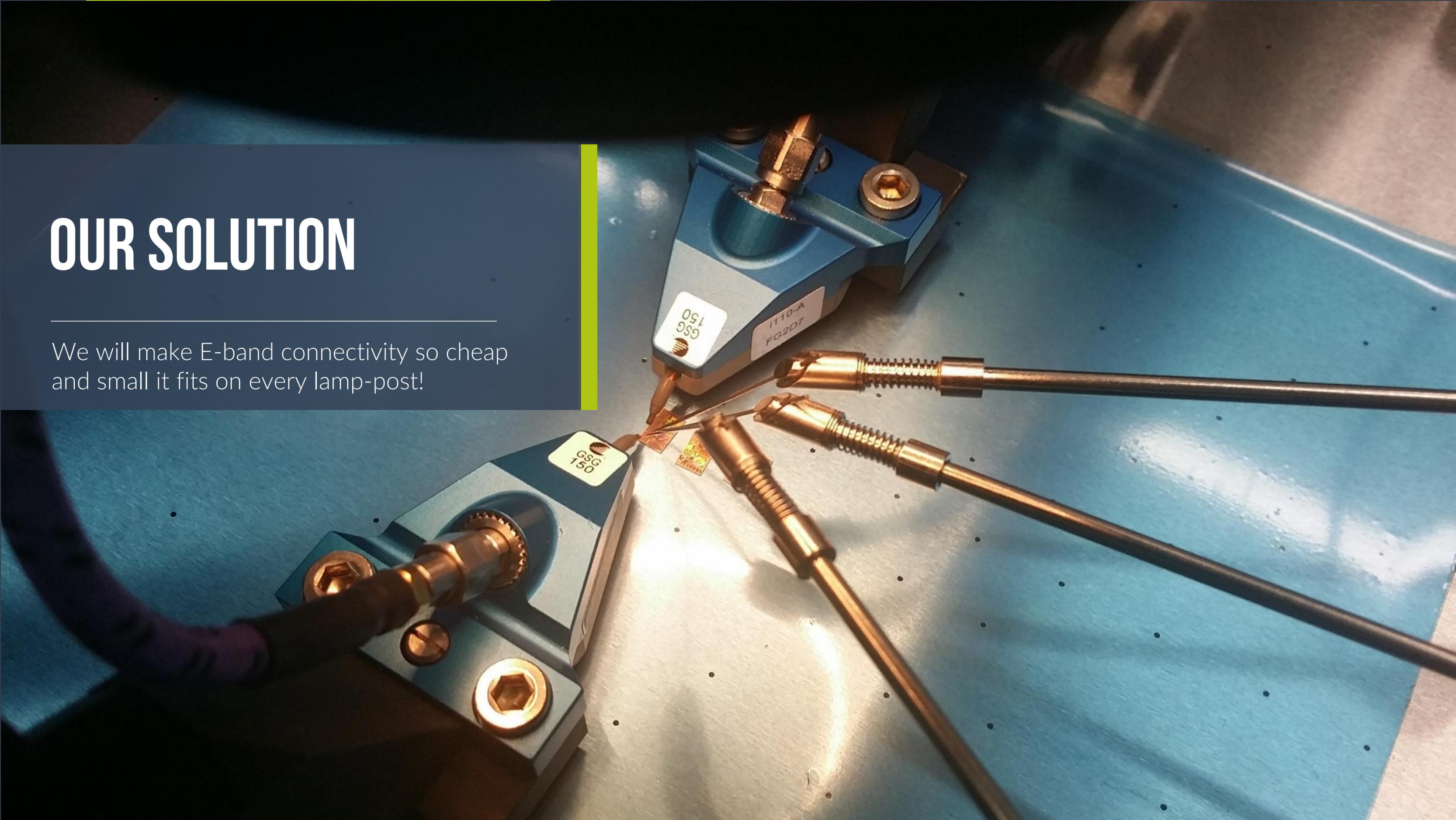
**Challenge areas**  
We're looking for solutions in the categories of Industry (helping businesses create new value for customers), Immersive Experiences (next-generation media and entertainment), and Moonshots (solving big problems with radical new ideas). Every submission should demonstrate the company's commitment to social responsibility and sustainable business practices.



Basically: they want apps that will make customers use their networks

# OUR SOLUTION

We will make E-band connectivity so cheap and small it fits on every lamp-post!



# OUR SOLUTION — INTEGRATION IN SILICON

Second generation

- Cheap
- Mass producible
- Low power
- Small

First generation



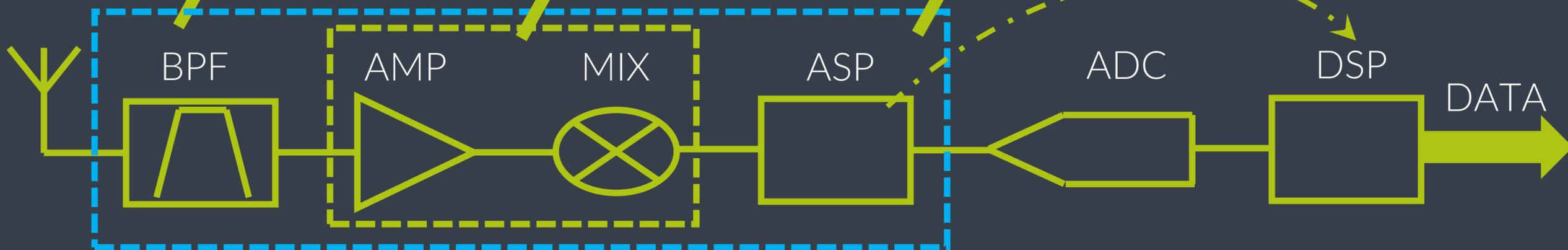
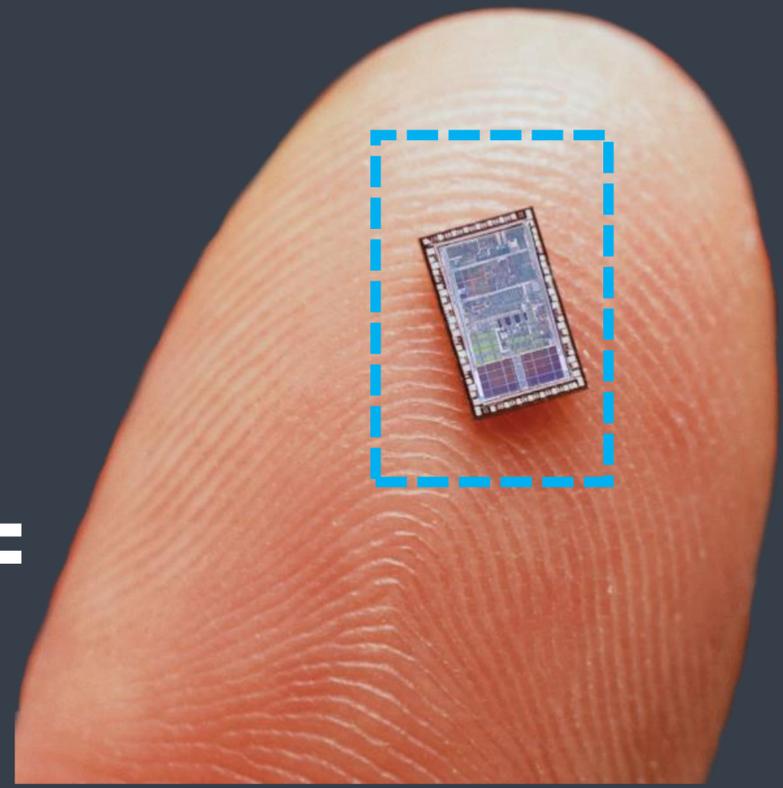
Thousands of \$ (IMA)



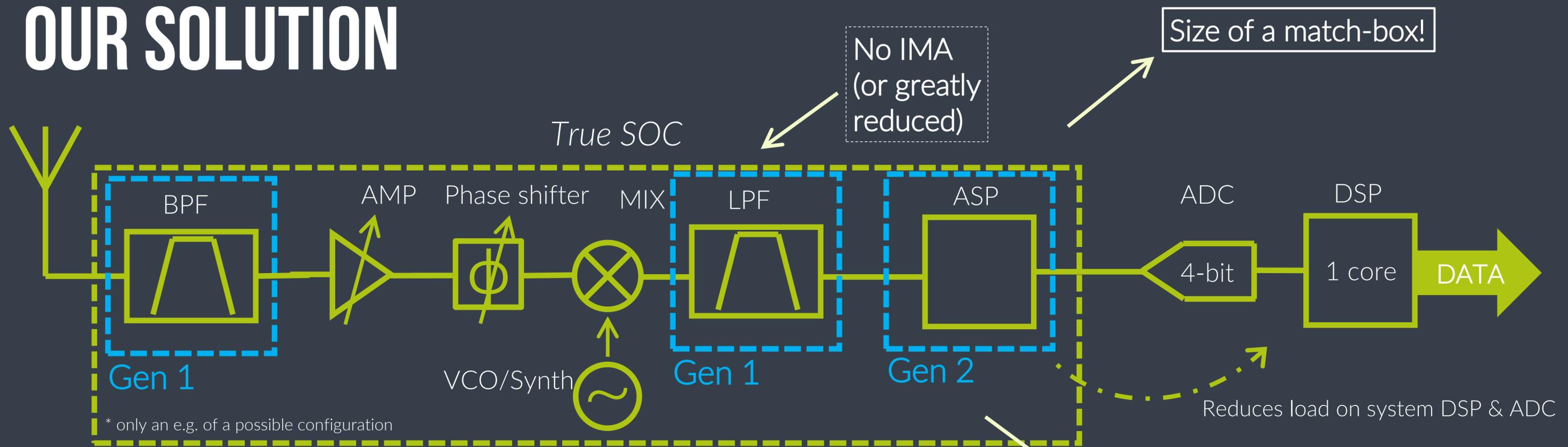
\$63



Thousands of \$  
Reduces load on DSP



# OUR SOLUTION



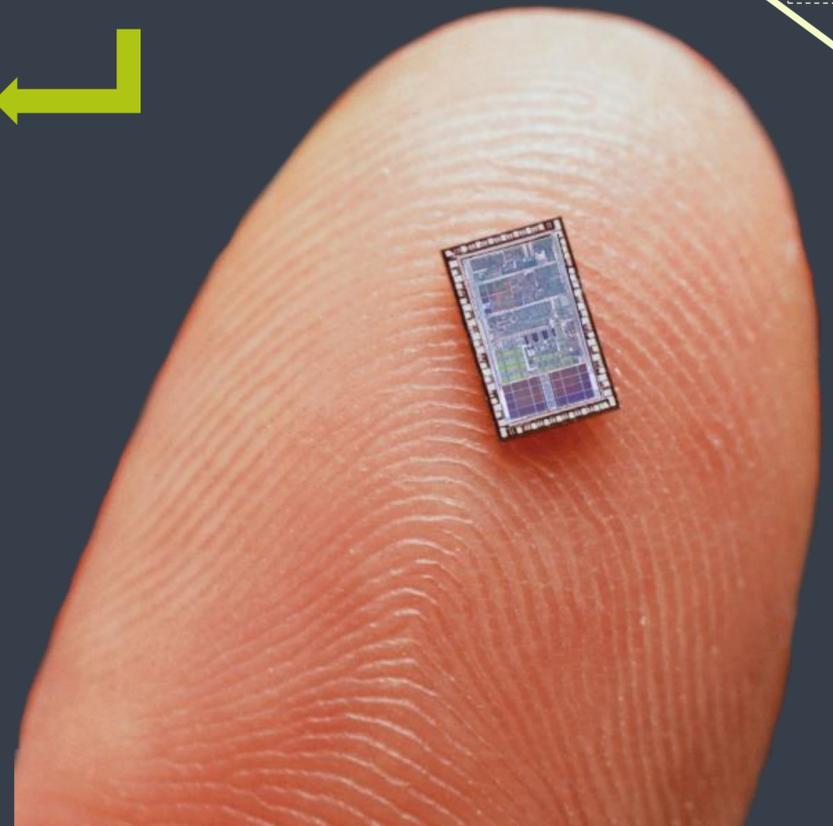
Our BPF & LPF is in Silicon (gen 1)

Our new ASP (gen 2)

- Stage 1: value add (evolutionary)
- No/less IMA:**
- Mass producible
  - Cheap
  - Small
  - Low power
  - Single chip
  - Perfectly suited for Small Cells and massive MIMO
  - Enhanced performance

Stage 2: value add (revolutionary)

- Enhanced performance
- Cognitive radio
  - Advanced beam steering (MIMO)
  - DCMA
  - Chanel equalization
  - RTFT (Range-Doppler)



# END PRODUCT COMPARISON

1. Single-chip TxRx front-end
2. With integrated tunable BPF
3. With analog signal pre-processing
4. This reduces size, cost and power consumption

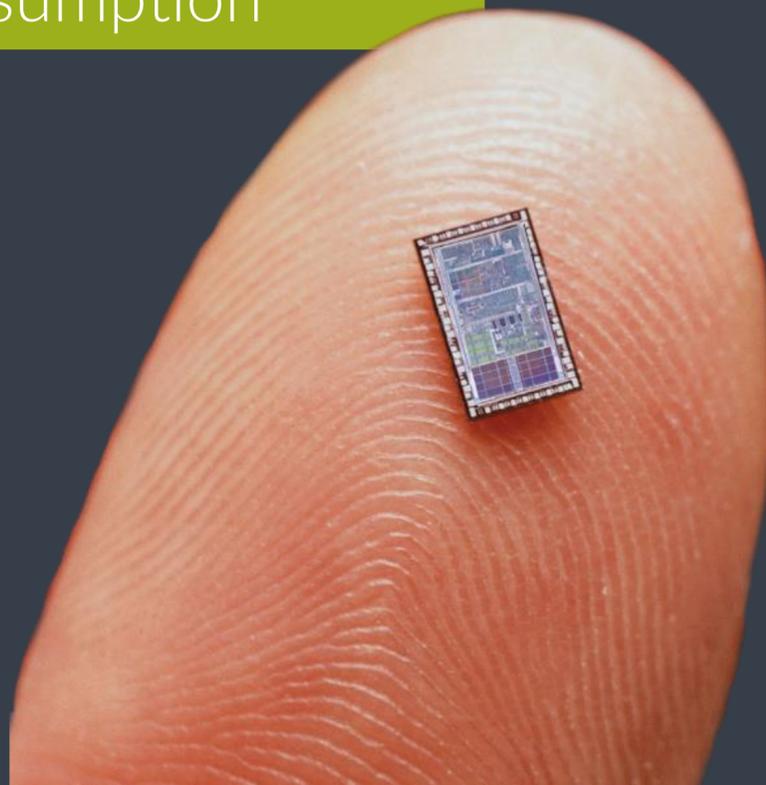
*We will make Gbps connectivity so cheap it will be on every light pole!*

Cheap (< \$1000)	Expensive (~ \$11,200)
------------------	------------------------

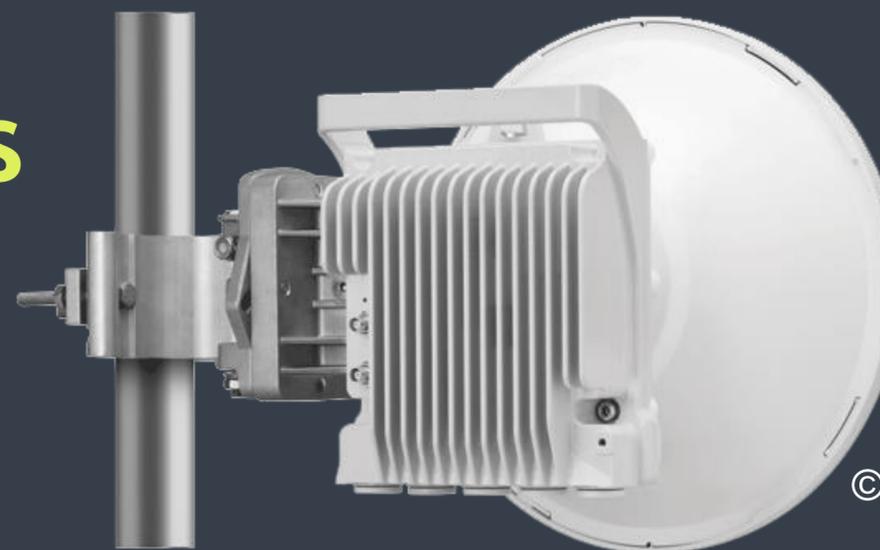
Low-power (<< 20 W)	Power intensive (~ 100 W)
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Small (< 5 cm x 5 cm)	Bulky (~ 25 cm x 25 cm)
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Mass producible	Low-volume
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**versus**



\*not to scale

# VALUE PROPOSITION

# VALUE PROPOSITION

## 1. Silicon BPF

### Existing solution

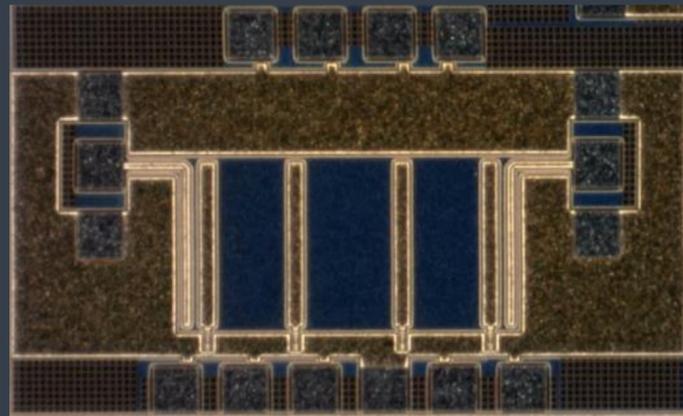


5 cm

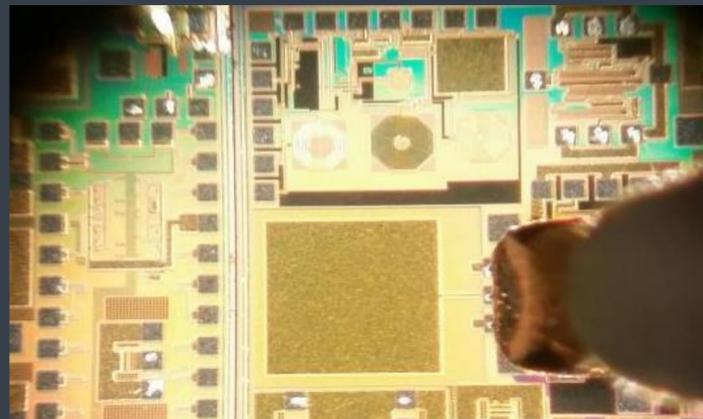


20 cm

### Our solution



300 microns



1 mm

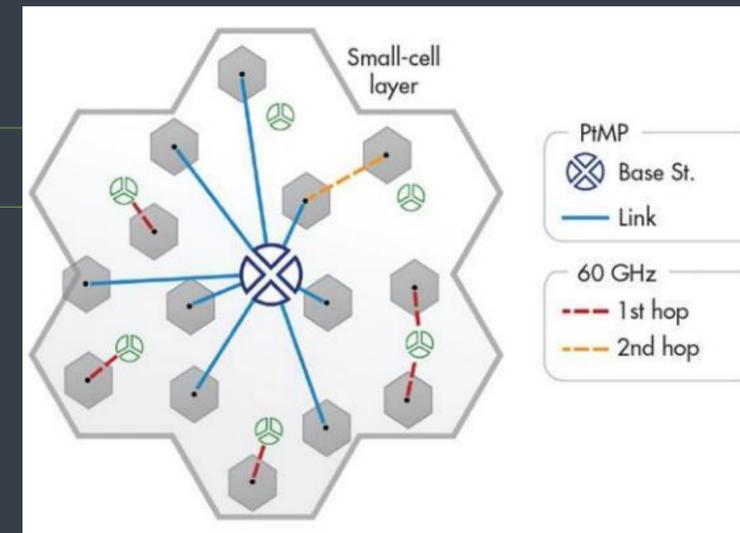
- Size & mass reduction x 100
- Monolithic integration enabled
- BOM reduction from
  - (2-8 individual filters)
  - (8-50 connectors and fasteners)
- No more hand tuning
  - Mass producible (easy to meet market demand)
  - Built in self tuning (BISTu)
- Cost benefits (IMA) – can be thousands of \$ per unit

# VALUE PROPOSITION

## 2. ASP: Real-time Fourier analysis for cognitive radio

- Real-time
- No need for FFT
- Large scanning bandwidth
- Low power
- Low-cost

Multifractal's solution	SOTA
Instantaneous analogue Fourier transform of a 3 – 9 ns sample window	Computation time on the order of $\mu\text{s}$ - C674x DSP: 256-pt FFT (16-bit) – 1.55 $\mu\text{s}$ , 512-pt FFT (16-bit) – 3.61 $\mu\text{s}$
Frequency resolution < 0.5 GHz @ $\Delta\tau = 3$ ns: <ul style="list-style-type: none"> <li>• 0.3 GHz @ <math>\Delta\tau = 6</math> ns</li> <li>• 0.1 GHz @ <math>\Delta\tau = 12</math> ns</li> </ul>	
Continuous bandwidth of 5 GHz per channel	Few hundred MHz
Dynamic range > 35 dB: @ $\Delta\tau = 3$ ns: <ul style="list-style-type: none"> <li>• &gt; 40 dB @ <math>\Delta\tau = 6</math> ns</li> <li>• &gt; 50 dB @ <math>\Delta\tau = 9</math> ns</li> <li>• 50+ dB @ <math>\Delta\tau = 12</math> ns</li> <li>• Noise considered</li> </ul>	~30 dB
Power consumption $\approx 0.1$ W (ADC) + ASP (< 50 mW) + x (mixer / mult) + x (LNA x 2) + x (envelope detector)	kW
Cost: soft substrate – few hundred \$	Thousands of \$
Cost: on-chip $\rightarrow$ cheap CMOS or BiCMOS (few cents per chip mass production)	-



### E.g.: Cognitive Radio



### E.g.: Automotive radar



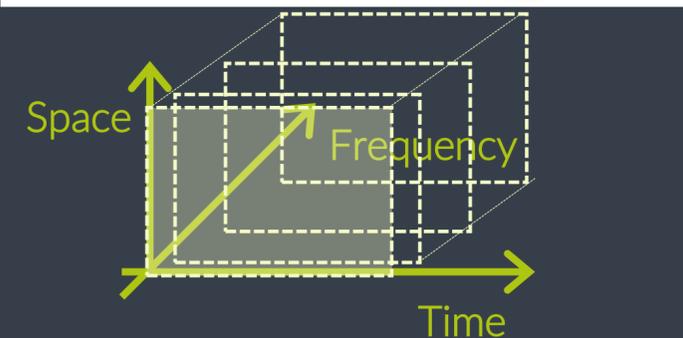
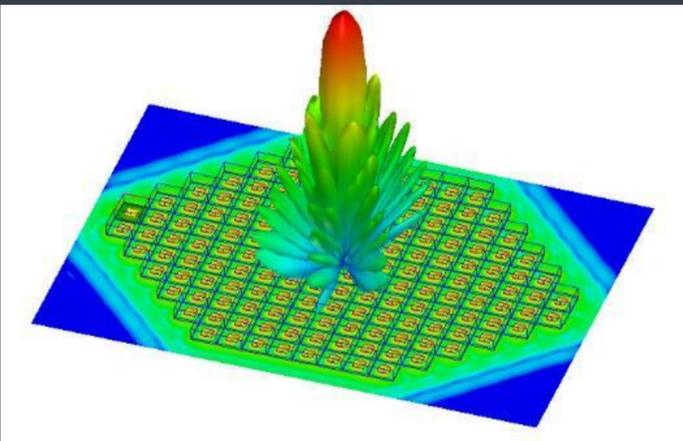
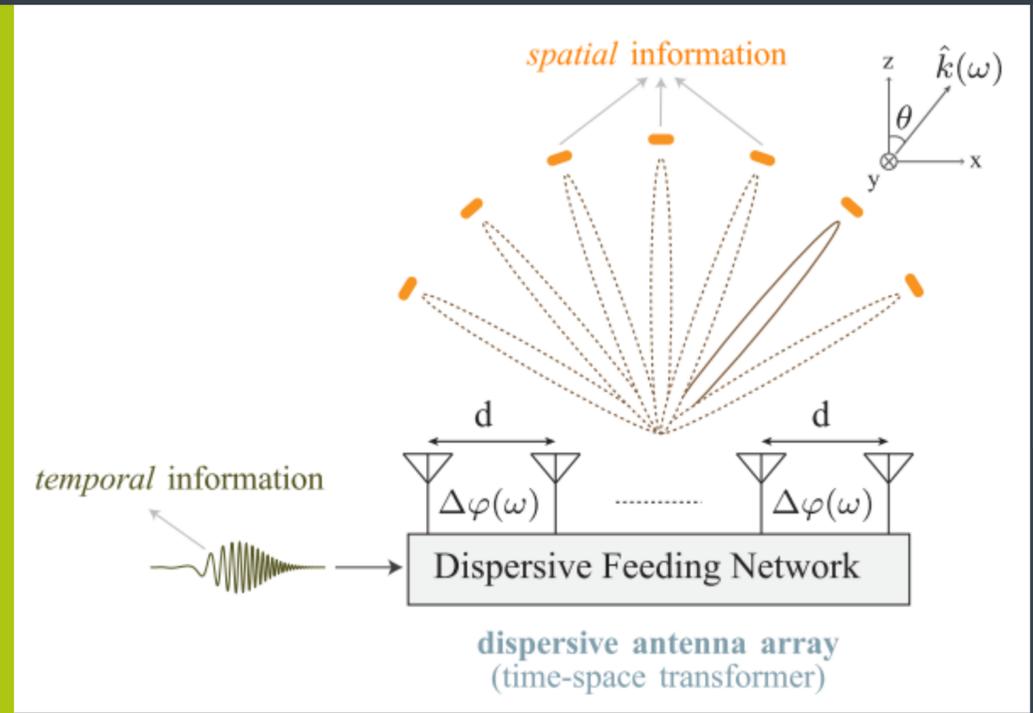
SOTA: resolution of 1m, maximum velocity of 30 m/s, few objects

# VALUE PROPOSITION

## 3. ASP: Advanced beam forming

- Arbitrary frequency beam steering
  - Steering angle controlled by frequency (carrier)
  - Continuously tunable (1 GHz BW - > 60 deg)
  - Specialized frequency to beam angle mapping possible
  - Low power – 20 mW per phaser (much lower than DSP solutions)
  - Low cost – CMOS and BiCMOS – support mass production

Even more Massive MIMO



### Automotive radar

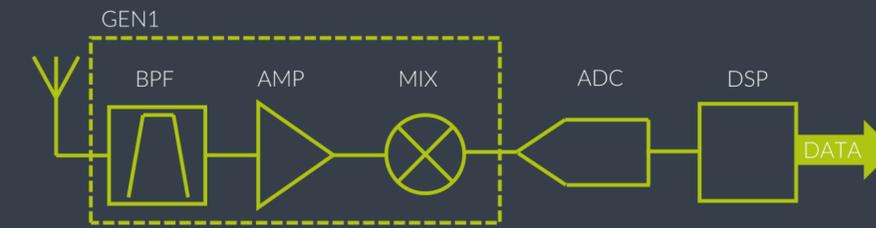


Multiple objects – SOTA 32

Wideband DDS can easily allow 60 deg to be mapped over 10 GHz allowing > 200 objects to be mapped each with 50 MHz fc control range

# GENERATION 1 FRONT-END (telecoms)

High-level specifications

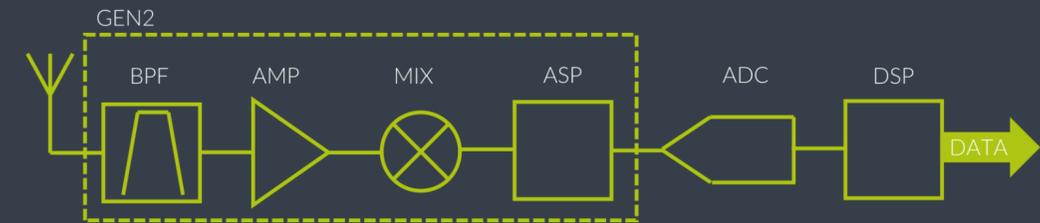


Parameter	Multifractal's gen 1 front-end	Siklu E-band front-end (EtherHaul 8010FX)	Our value add
Power consumption	< 2 W	50 W (including DSP)	10-20X power reduction
Cost	Tens of \$	~\$ 11k	>100X cost reduction
Channel bandwidth	5 GHz	2 GHz	SoC solution – fewer components, higher bandwidth, lower power
Throughput	10 Gbps full duplex	10 Gbps full duplex (FDD)	-
RF bands	71-76, 81-86 GHz	71-76, 81-86 GHz	-
System gain	80 – 98 dB	64 – 93 dB	-
Range	300 m	2.73 – 3.7 km	Small cell densification
Operating temperature	-45 to +85°C ++	-45 to +55°C	Single chip solution – better temperature performance / match
Dimensions	~ 10 by 10 cm (with MIMO array) – RF module (~5x5 cm)	~ 30 by 30 cm (single antenna – no MIMO)	Massive MIMO
Weight	< 100 g	~ 5 kg	Small, lightweight
NF	~5 dB	?	Relaxed requirements due to small cell dens.

Smaller range has benefits – our solution allows for this small cell dens. due to lower costs, power and size

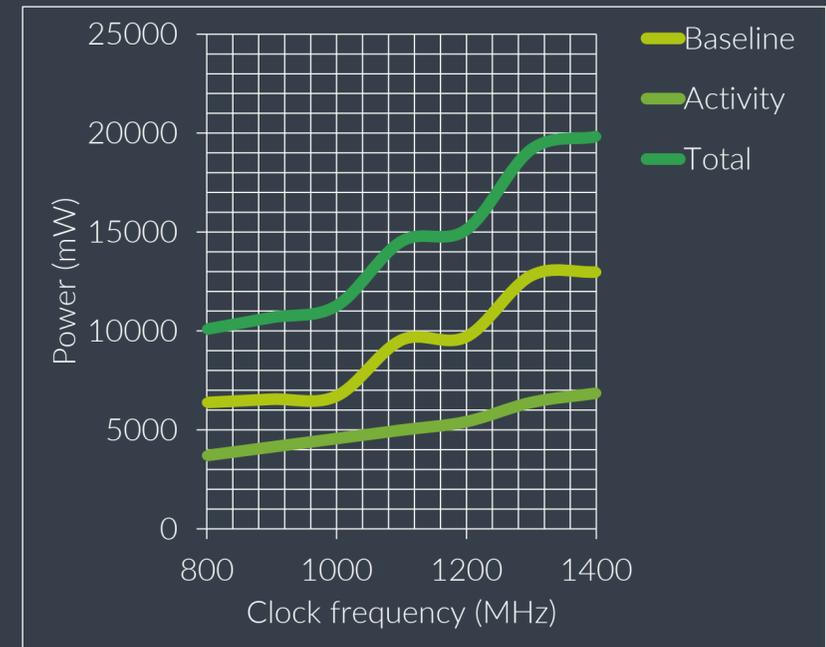
# GENERATION 2 FRONT-END (telecoms)

High-level specifications (ASP only – **cognitive radio** – other specs stay the same)



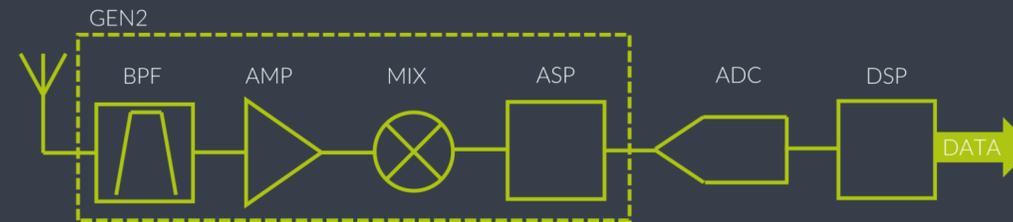
Existing solution do not scale well with bandwidth TI 66x (8 cores)

Parameter	Multifractal's IC	TI's AWR1243 / DSP 66x series or equivalent	Our value add
Power consumption	< 20 W (incl. DSP)	> 100 W (incl. DSP)	5-10X reduction
Cost	Hundreds of \$	Thousands \$	>100X reduction
Processing speed	< 50 ns per FFT	> 1 μs per FFT (1 core)	50X improvement (faster multiple object detection)
IF bandwidth (automotive radar)	1-4 GHz	5 MHz	100X faster (faster detection)
RF bandwidth (automotive radar)	4 – 8 GHz	4 GHz	2X larger → 2X resolution (4.5cm → 2.25 cm)
Complexity	Final system design = simple/no IMA!	Final system design = complex IMA	Supports mass production, lower production costs
Dynamic range	50 dB	~50 dB	-
ENOB	4	8	Relaxed ADC requirements
Equivalent n-points	70 (current technology with the aim to improve)	-	-
Power accuracy	±3 dB	~ 1 dB	-
Frequency accuracy	~ 100 Mhz	~ 100 MHz	-
Magnitude / phase information	Magnitude only	Both	Application dependent

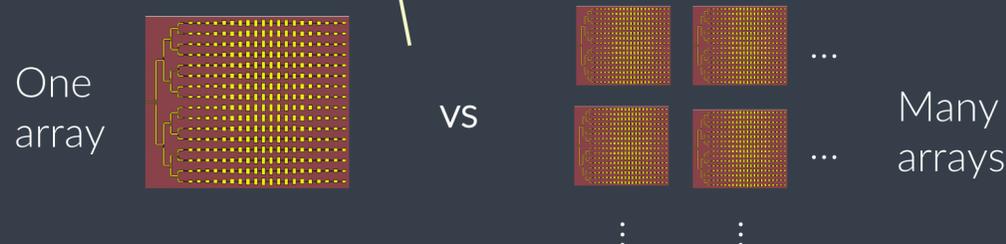
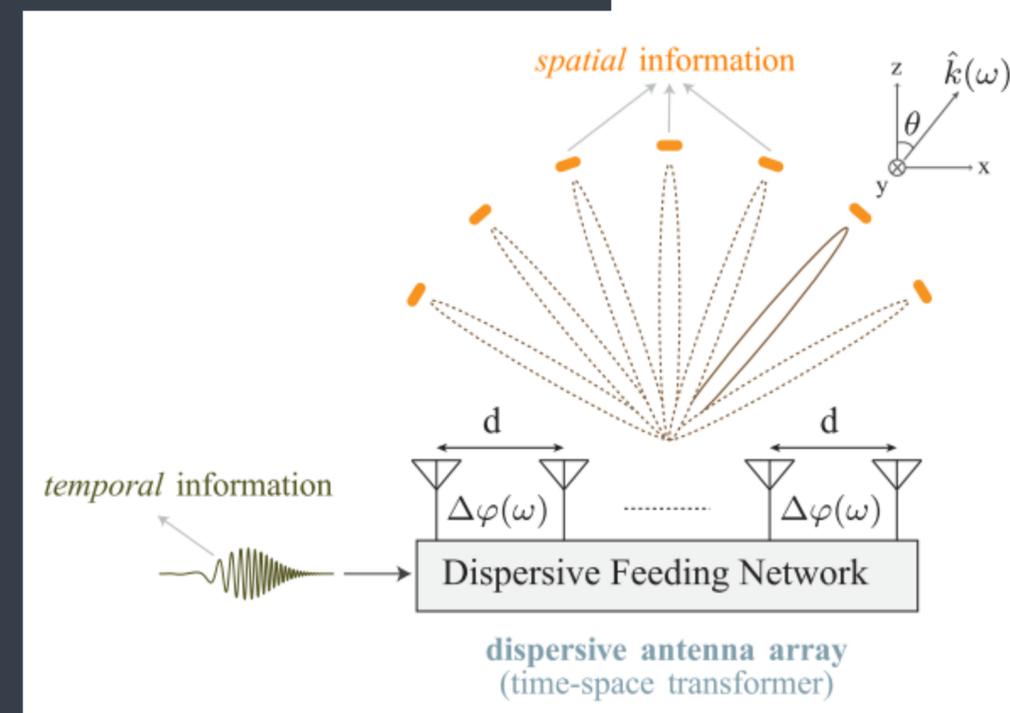
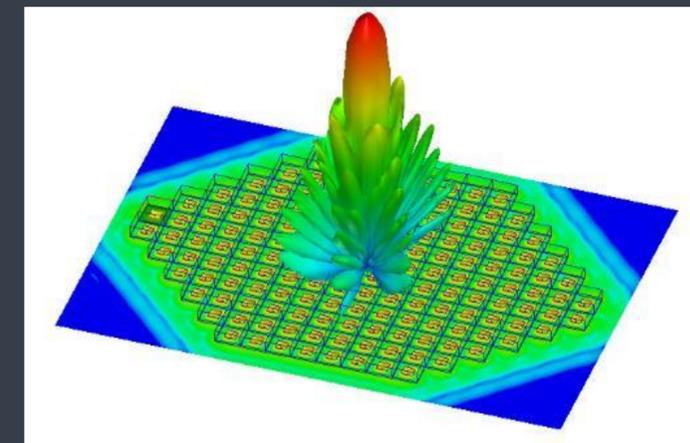
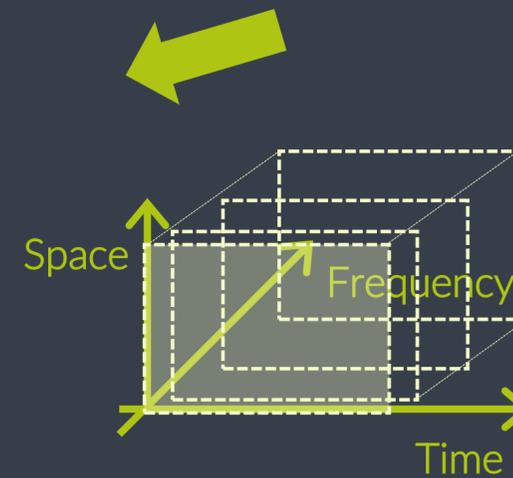


# GENERATION 2 FRONT-END (telecoms)

High-level specifications (ASP only – frequency beam steering – other specs stay the same)



Parameter	Multifractal's IC	TI's AWR1243 / DSP 66x series or equivalent	Our value add
Power consumption	< 20 W (incl. DSP)	> 100 W (incl. DSP)	5-10X reduction
Cost	Hundreds of \$	Thousands \$	10X reduction
Processing speed (tracking speed)	< 50 ns per operation	> 1 μs per operation (1 core)	50X improvement (faster steering)
Complexity	Final system design = simple/no IMA!	Final system design = complex IMA	Supports mass production, lower production costs
Dynamic range	50 dB	~50 dB	-
Bandwidth	> 8GHz	4 GHz is already a challenge	-
Channels per antenna (frequency mapped to angles)	> 30 (only one array! – one tile)	? (Unheard of) – many tiles / antenna arrays needed	More massive MIMO! Truly big data.
Frequency reconfigurability (lens effect)	8 GHz band → 100 MHz band	Unheard of	Frequency lensing



# BUSINESS MODEL & EXEC

What we've done and where we're going.



# OVERVIEW & FOCUS

How will we make money?

## Applications

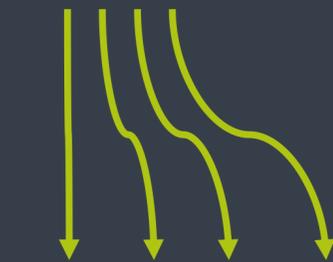
- Communications
- Sensing

## Markets

- 5G Backhaul & Fronthaul
- Fixed wireless access
- 5G Access
- Automotive radar

## Costs

- Design
- Manufacture
- Sales
- Distribution



## Products

- Full F/E as Chip
- Components as SiP
- Full F/E as SiP

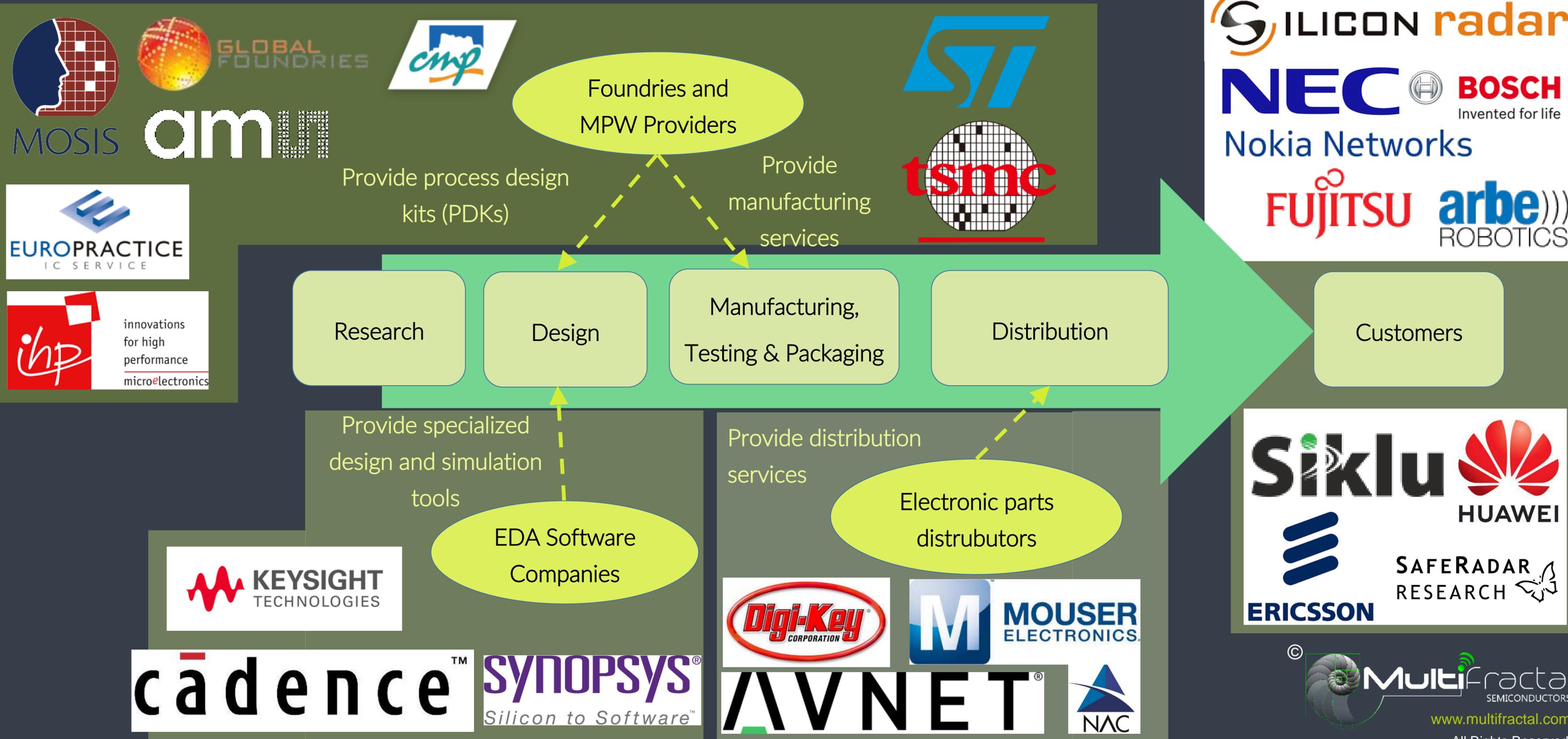
## Revenue streams

- Chip sales
- IP Licenses
- Services



# KEY PROJECT SUPPLIERS & PARTNERS

in the context of our value chain



# EXECUTION TIMELINE

Proof of Concept  
& Incorporation

First samples  
delivered to  
customers



2014

Research  
began



2017

Raising funding  
for product  
development



2018



2020

Full scale  
manufacture



2021

# EARLY CUSTOMERS & TRACTION

Interested in E-Band F/E for telecommunications.  
LOI provided. Waiting for samples.



Interested in E-Band BPF (& other F/E components) for single chip CMOS radar. LOI imminent. Waiting for samples.

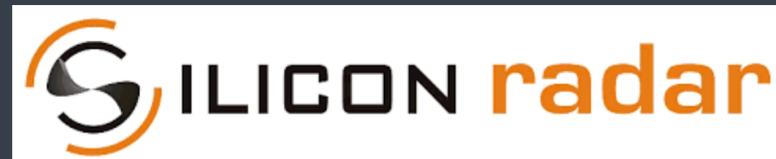


Interested in ASP for defence (analog FFT).  
Paying \$ 50 k for NRE.



**Saab Grintek**

Prospective:



# FUNDING TIMELINE

What has been done so far?

Bootstrapped  
\$ 10 k

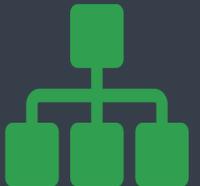
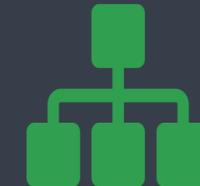


SAAB NRE  
\$ 50 k

Confirmed - full support!



Almost finalized  
(term-sheet)



2017

2018 Q1

2018 Q4

2018 Q4

2019 Q1

GAP ICT & TelAviv SA  
Winner  
\$ 20 k

Si Catalyst in-kind  
support  
\$ 1.6 M

StarFinder &  
Vigo Systems  
\$ 1.6 M



TEL AVIV NONSTOP CITY

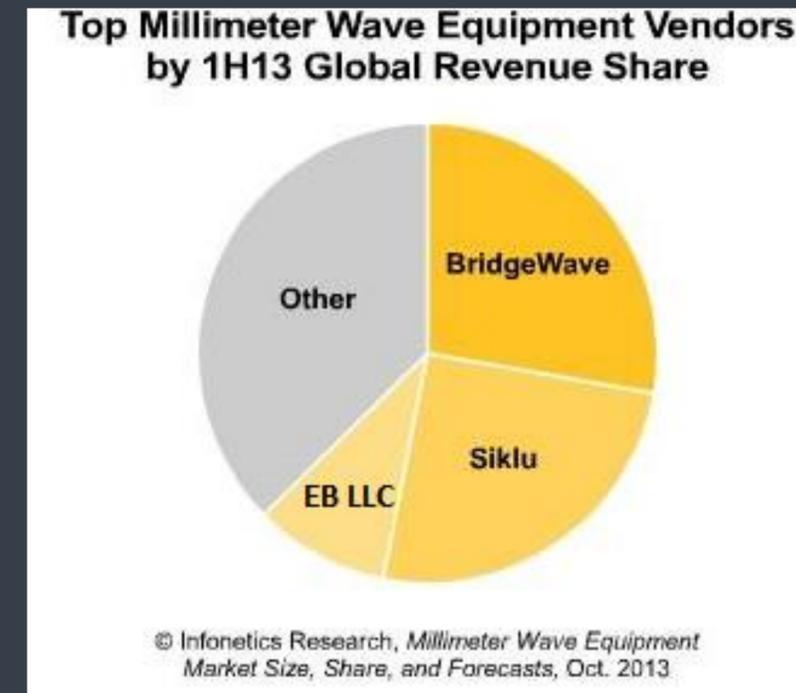


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# FINANCIALS – MARKET PROJECTIONS (SAM)

Year	TAM	CAGR
2017	\$400 000 000,00	38,85%
2018	\$555 400 000,00	38,85%
2019	\$771 172 900,00	38,85%
2020	\$1 070 773 571,65	38,85%
2021	\$1 486 769 104,24	38,85%
2022	\$2 064 378 901,23	38,85%
2023	\$2 866 390 104,36	38,85%



- Existing: single link = 10 000 USD
- Multifractal’s disruptive product will bring single link down to 1000 USD
- Drastically raise the volumes shipped. Based on this:
  - our projections indicate a market share of 9.69% in year 4 growing to 15.08% in year 6

# FINANCIALS — EXPECTED REVENUE (SOM)

	Year 1	Year 2	Year 3	Year 4	Year 5	Year 6	Year 7	Year 8
Theme	1. Lean development			2. Production ramp-up		3. Full - Production		
Objectives	1.1. Develop tech 1.2. Develop market 1.3. Produce and distribute samples			2.1. Develop product 2.2. Develop sales and distribution channels 2.3. Full wafer production		3.1. Grow market share 3.2. Grow product line		
Revenue	\$0	\$0	\$0	\$7,360,000	\$19,200,000	\$28,400,000	\$33,950,000	\$47,700,000
Costs	\$555,579	\$538,678	\$514,646	\$5,349,016	\$8,064,634	\$12,678,928	\$15,063,663	\$17,675,697
Profit	-\$555,579	-\$538,678	-\$514,646	\$2,010,984	\$11,135,366	\$15,721,072	\$18,886,337	\$30,024,303
Cashflow	\$1,053,324	\$514,646	\$4,895,057	\$6,906,041	\$18,041,406	\$33,762,478	\$52,648,815	\$82,673,118
Investment	\$1,608,903		\$4,895,057					
	<i>Technology development</i>			<i>Commercialization</i>				

Tech development funding - \$ 1.6 M

Commercialization grant - \$ 5 M

# QUARTERLY BUDGET

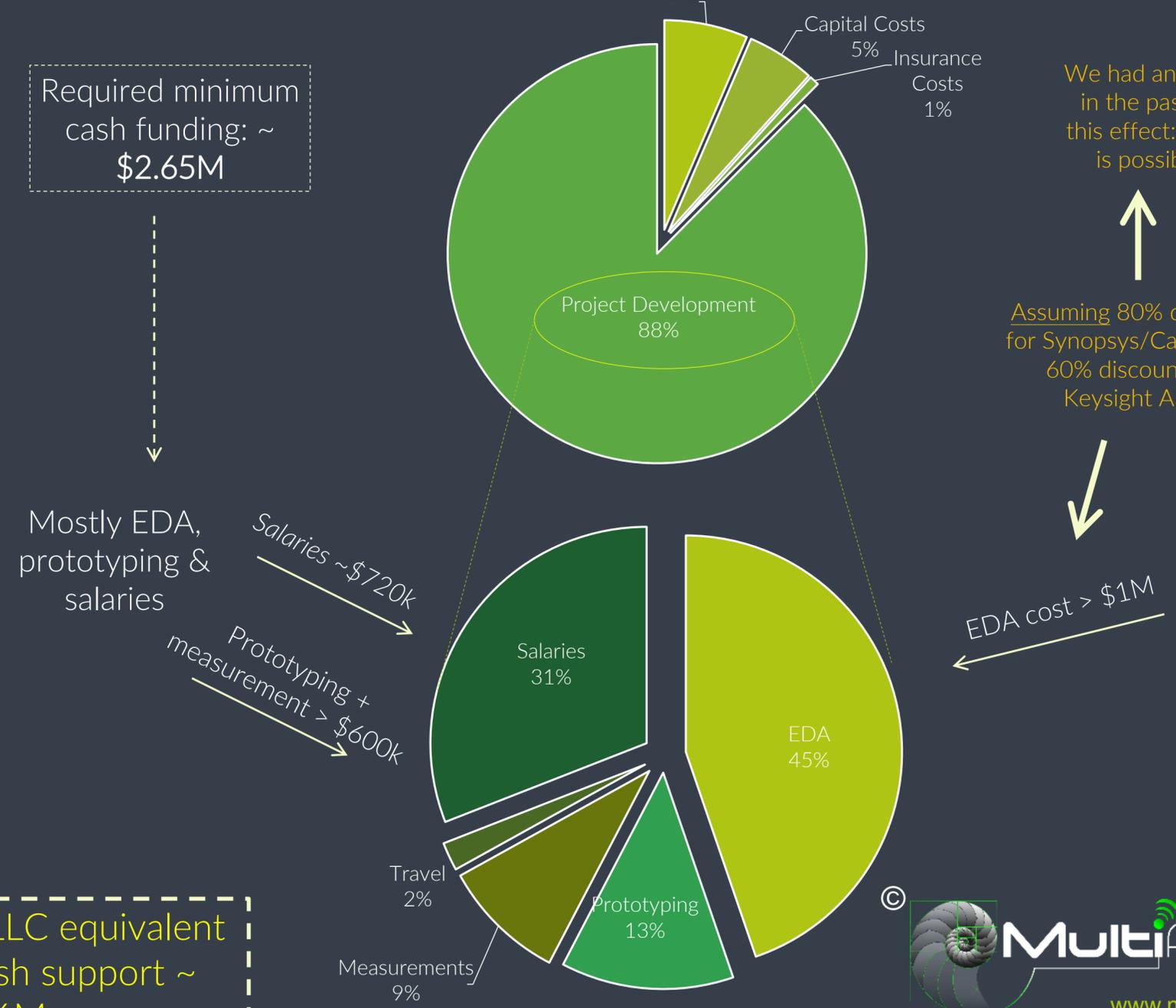
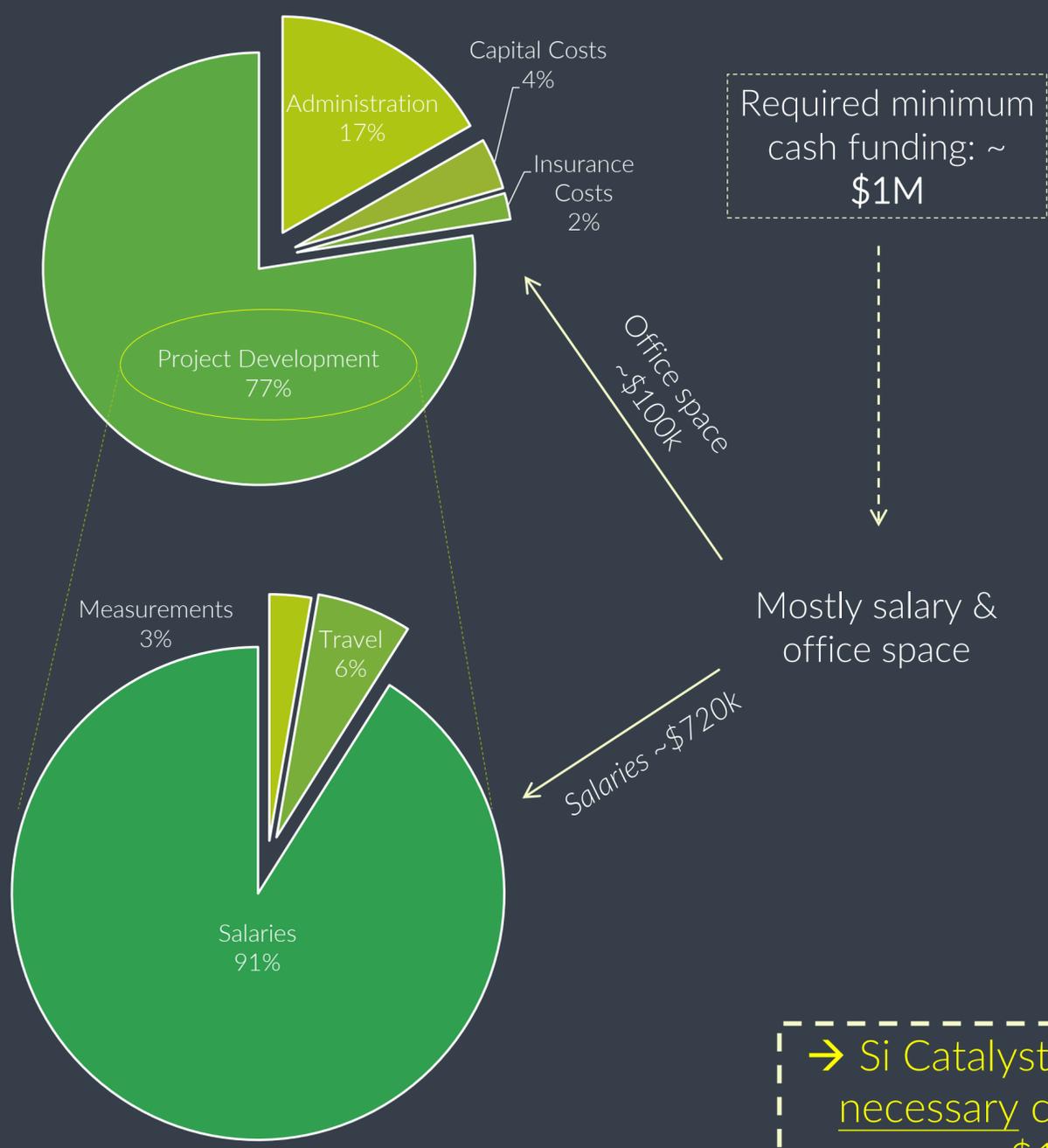
## COMPARISON



With Si Catalyst support



Without Si Catalyst support



→ Si Catalyst LLC equivalent necessary cash support ~ \$1.6M

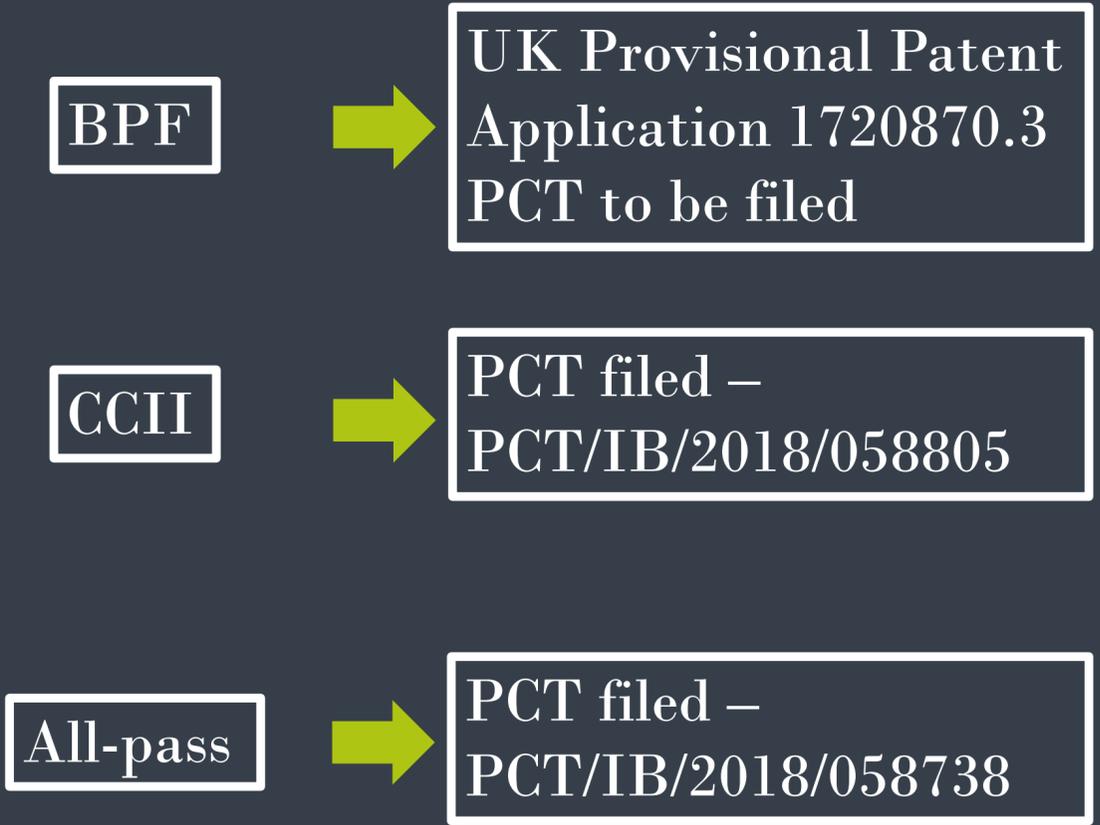
We had an offer in the past to this effect: i.e. it is possible

Assuming 80% discount for Synopsys/Cadence & 60% discount for Keysight ADS

# IP STRATEGY

IP has been licensed from the University of Pretoria – exclusive lic.

To licence or not licence? That is the question.



- New IP to be developed in the future addressing shortcoming of previous generation implementations
- Freedom to Operate as this will be novel IP

Patent: countries to be filed in, in this order:

# TEAM INTRODUCTION



**Dr Piotr Osuch**  
CTO & Co-founder



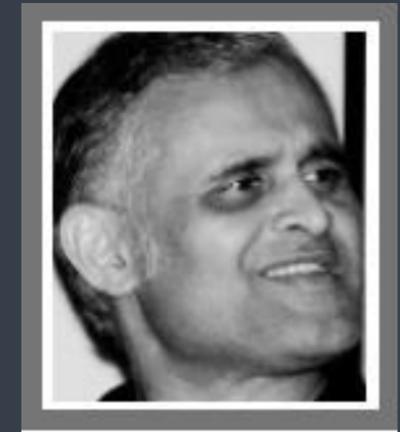
**Nish Singh**  
COO & Co-founder



**Hendrik Nel**  
RFIC engineer



**Dr Tinus Stander**  
Tech. Advisor



**Dinesh Maheshwari**  
Biz. Advisor



CA, USA

- CTO: Memory Division, Cypress Semiconductor
- Board of Directors at JEDEC, UPA; Advisory Board at Kandou Bus, Deca Technologies, Zeno Semiconductor, Tutenna.
- Technologist at Silicon Light Machines, Synopsys, Mentor Graphics, Cadence, Microprocessors & Controls LLC
- ~30 years of Technology, Market and Business strategy in Semiconductors, Systems and Software

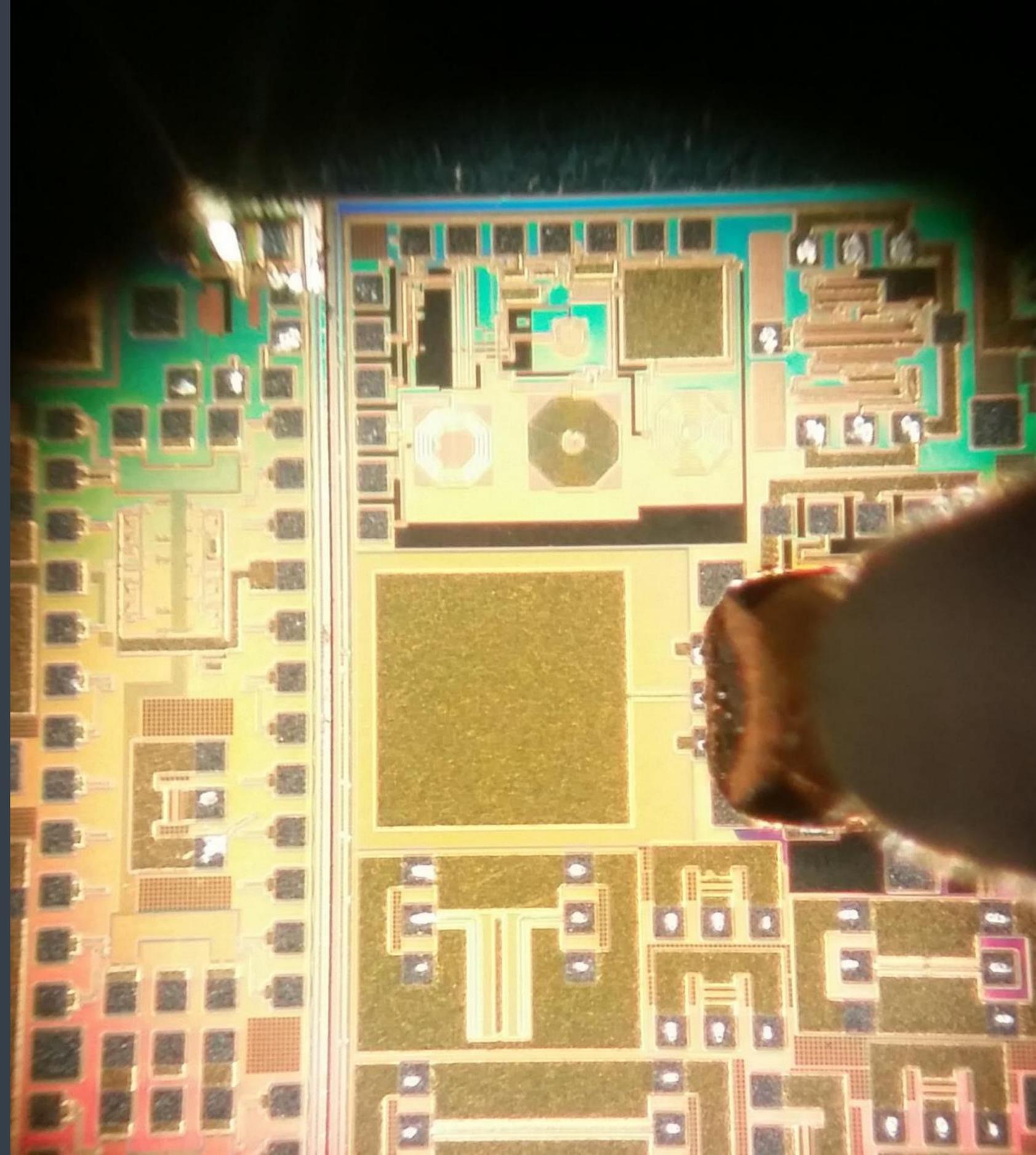
# STAY CONNECTED

We look forward to forming a partnership

 Address  
Pretoria, South Africa

 Contact Info  
Nish: [nish@multifractal.org](mailto:nish@multifractal.org)  
Piotr: [piotr@multifractal.org](mailto:piotr@multifractal.org)

 [twitter.com/multifractal\\_sa](https://twitter.com/multifractal_sa)



# APPENDIX — POTENTIAL COMPETITORS

# POTENTIAL COMPETITORS (automotive)

Texas Instruments  
AWR1243



- AWR1243 - 76-to-81GHz high-performance automotive MMIC
- RF (chirp) bandwidth = 4 GHz → range resolution ~ 4.5 cm
- Cross-range resolution @ max range ~ 70 cm
- IF bandwidth = 5 MHz → ~1-40 ms per computation cycle (refresh rate)
- Cost: \$36 per IC, power: a few W.
- Requirement: powerful DSP for 2D-FFT (range-Doppler): for each TxRx pair! Recommended TI C66x:
  - ~ 20 W per core to do 64 point FFT in 1  $\mu$ s (1.4 GHz)
  - A few cores will be required:
    - 8 cores: → 140 W – 160 W
    - 16 cores: → 320 W
  - Few thousand \$ (ADC+DSP+etc.) ~ \$3k

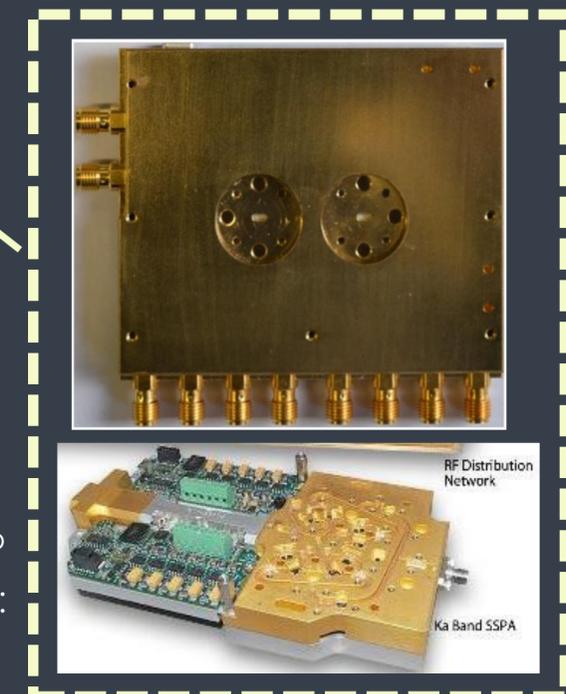
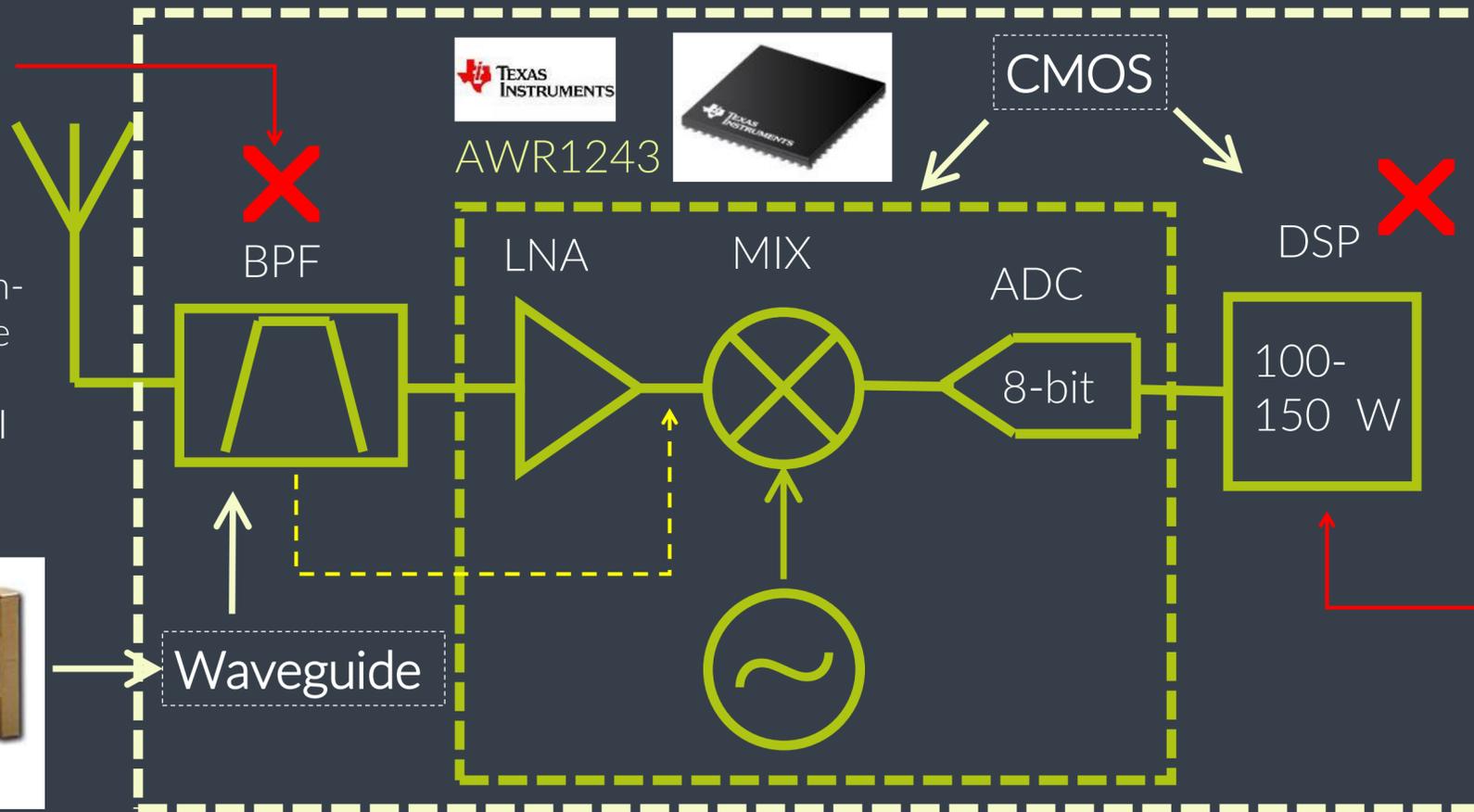


Multifractal's technology will improve on this significantly / add value

∴ TI can be a potential partner or even customer

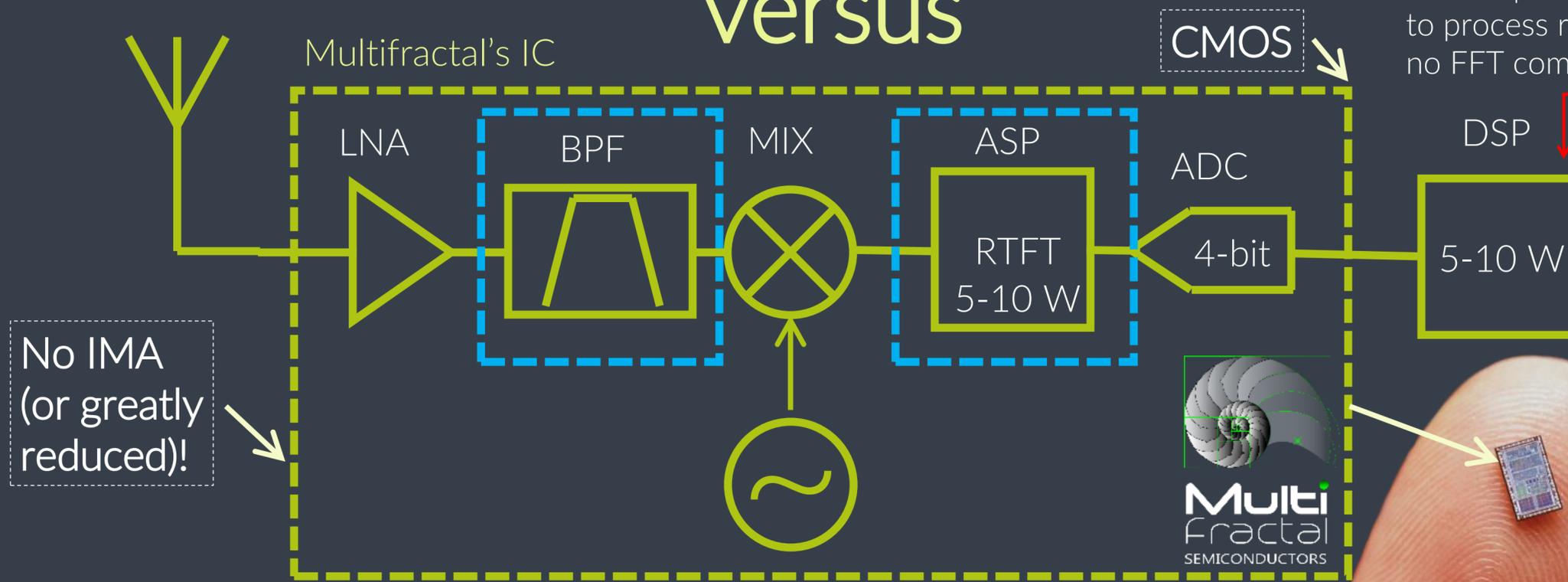
See next slides for details ...

A pre-select filter will be required – because in future, E-band will be busy! (e.g. telecoms signals). Otherwise, out-of-band signals will mix in-band. The filter should be after LNA & before MIX, as shown (yellow), for full benefit.



Powerful DSP Required, see: datasheet

# versus



Much less powerful DSP required – only to process result – no FFT computation

# POTENTIAL COMPETITORS (automotive)

Texas Instruments  
AWR1243



Parameter	TI's AWR1243	Multifractal's IC	Our value add
Power consumption	> 100 W (incl. DSP)	< 20 W (incl. DSP)	5-10X reduction
Cost	Thousands \$	Hundreds of \$	100X reduction
Processing speed	> 1 $\mu$ s per FFT	< 50 ns per FFT	50X improvement (faster multiple object detection)
IF bandwidth	5 MHz	1-4 GHz	100X faster (faster object detection)
RF bandwidth	4 GHz	4 – 8 GHz	2X larger $\rightarrow$ 2X resolution (4.5cm $\rightarrow$ 2.25 cm)
Complexity	Final system design = complex IMA	Final system design = simple/no IMA!	Supports mass production, lower production costs

# POTENTIAL COMPETITORS (telecoms)

Tusk IC NV (Antwerp, Belgium)



- Founded in January 2018 as a spin-off from the KU Leuven ESAT-MICAS research group
- Technology (40 nm CMOS) - [link](#):
  - A Push-Pull Complementary mm-Wave Power Amplifier
  - Waveguide receiver
  - ~0.5 THz signal generators (also in 28nm CMOS)
  - 60 GHz outphasing transmitter (PA with high efficiency)
  - 120 GHz quadrature frequency generator (45 LP CMOS)
  - 118 GHz VCO (65nm CMOS)
  - 200 GHz downconverter (90nm CMOS)

Infineon IC: E-band (60-90 GHz)

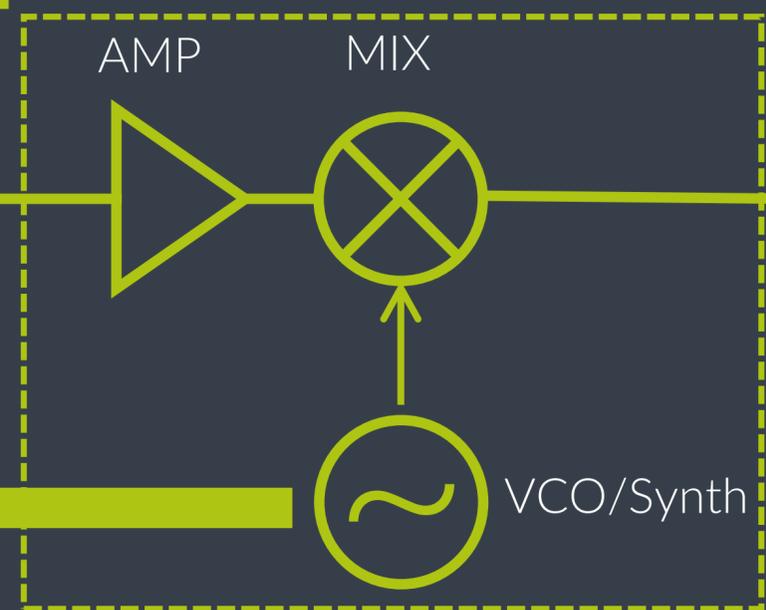


\$63

e.g.

They have many competitors w.r.t. the AMP and MIX IP

summary



Tusk IC value add is mainly in VCOs and signal generation:

- MACOM VCOs → ~15 GHz
- ANALOG VCOs → ~27 GHz
- Texas Instruments VCOs → ~20 GHz



Not part of Multifractal's value proposition (BPF & ASP)  
 ∴ Tusk IC could be a potential partner or even customer



# POTENTIAL COMPETITORS (telecoms)

Anokiwave (CA, USA)

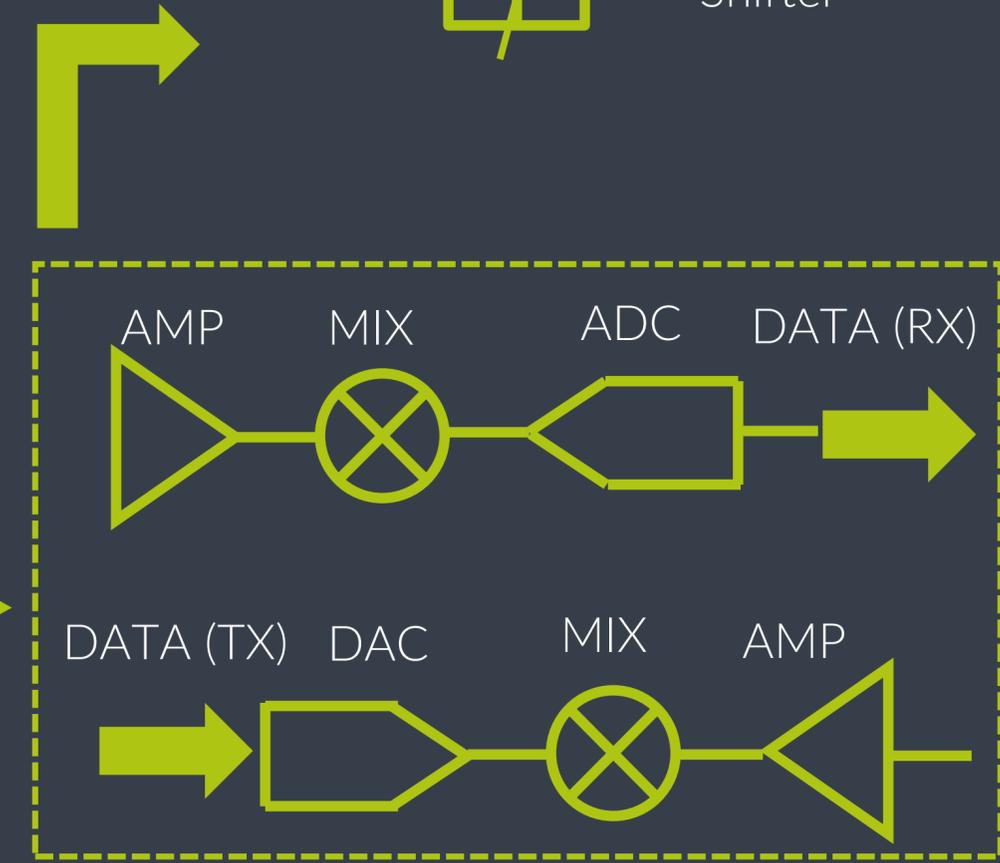
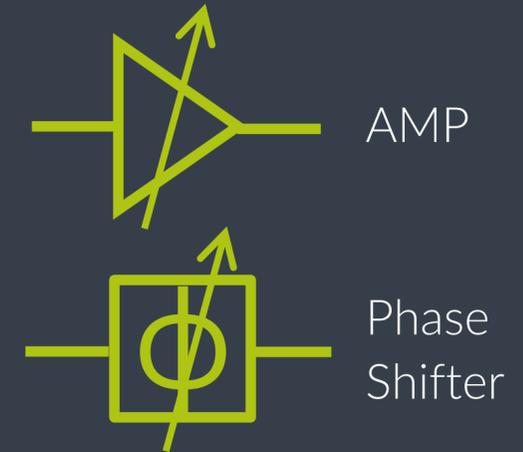


- Founded in 1999
- Technology – [link](#):

Market	Band	Product Family	Description
5G Communications Active Antennas	24/26 GHz	Silicon Core IC	5G Tx/Rx Quad Core IC
			5G Tx/Rx Quad Core IC
	28 GHz	Silicon Core IC	5G Tx/Rx Quad Core IC
			5G Tx/Rx Quad Core IC
	37/39 GHz	Silicon Core IC	5G Rx Quad Core IC
			5G Tx Quad Core IC
5G Tx/Rx Quad Core IC			
Active Antenna Innovator Kits	24/26 GHz	Active Antenna	256 Element Innovator Kit
	28 GHz	Active Antenna	64 Element Innovator Kit 256 Element Innovator Kit
RADAR and Communications Active Antennas	X-Band	Silicon Core IC	Dual Beam Low NF Tx/Rx Quad Core IC
			Dual Beam High IIP3 Tx/Rx Quad Core IC
			Single Beam Low NF Tx/Rx Quad Core IC
			Single Beam High IIP3 Tx/Rx Quad Core IC
		RF Front End IC	Medium Power Front End MMIC
SATCOM Active Antennas	K-Band	Silicon Core IC	4-element Dual Pol Rx Quad Core IC
	Ka-Band	Silicon Core IC	4-element Dual Pol Tx Quad Core IC
		PA IC	3W High Power Amplifier MMIC
Multi-Market	Ku-Band	Silicon Core IC	Intelligent Gain Block IC w/ SW
			Intelligent Gain Block IC w/o SW
	Ka-Band	Silicon Core IC	Intelligent Gain Block IC w/ SW
			Intelligent Gain Block IC w/o SW
Point-to-Point Radio Communications	E-Band	LNA IC	Low Noise Amplifier MMIC

Anokiwave's primary value add is in tunable AMPs and Phase Shifters (X, Ku, K, Ka).

At E-band they have a tunable AMP



summary →

Not part of Multifractal's value proposition (BPF & ASP)  
 ∴ Anokiwave is most probably a future partner



# POTENTIAL COMPETITORS (telecoms)

## Other interesting research

- mmWave Circulator IC
  - Columbia Engineering researchers in collaboration with UT-Austin
  - First magnet-free non-reciprocal circulator on a silicon
  - Value proposition: saving real-estate and costs for full-duplex COM ICs
  - Early-stage research (many performance metrics unknown)
  - Existing competitors: none on-chip. There are some products in waveguide such as smiths interconnect.
  - Existing technology uses switches for full-duplex – similar to what they do.
- What does this mean for Multifractal:
  - Not part of our value proposition
  - If they commercialize they could become potential partners
  - ... or we could commercialize similar tech before them



# APPENDIX — HIGH-LEVEL END-PRODUCT SPECIFICATIONS

# LINK BUDGET (telecoms)

## Low-level requirements

Center frequency (GHz)	73.50
PA output power (dBm)	20.00
Number of PAs	32.00
<b>Total output power (dBm)</b>	<b>35.05</b>
Number of Tx antenna elements	64.00
Tx antenna element gain (dB)	10.00
Antenna & feed network loss (dB)	4.00
<b>Total Tx antenna array gain (dB)</b>	<b>24.06</b>
<b>EIRP (dBm)</b>	<b>59.11</b>

Distance (m)	300.00
Att no rain (dB/km)	0.50
Att rain 5mm/h (dB/km)	3.00
Att rain 25mm/h (dB/km)	10.00
Att rain 150mm/h (dB/km)	40.00
Att no rain (dB)	0.15
Free space loss	119.31
Path loss (urban)	144.33
Total Path loss (dB) (no rain)	144.48
Total Path loss (dB) (light rain)	145.23
Total Path loss (dB) (heavy rain)	156.33

<b>Received power norm (dBm)</b>	<b>-85.37</b>
<b>Received power worst (dBm)</b>	<b>-97.22</b>
Bandwidth (MHz)	2000.00
Operating temperature (celsius)	100.00
Thermal noise floor (dBm)	-79.87
Noise Figure (dB)	5.00
SNR (dB) per Rx antenna element	-10.50
Number of Rx antenna element	64.00
Rx antenna element gain (dB)	10.00
Rx antenna feed network loss (dB)	3.50
<b>Total Rx antenna array gain (dB)</b>	<b>24.56</b>

SNR after beamforming (norm) (dB)	14.07
SNR after beamforming (worst) (dB)	2.22
Signal power - S (W)	8.30E-10
Signal power worst - S (W)	5.42E-11
Noise power - N (W)	3.26E-12
Eb/no (QPSK) - dB	5.00
BER	5.95E-03
<b>Rb (max bit rate no rain) (gbps)</b>	<b>161.27</b>
<b>Rb (max bit rate heavy rain) (gbps)</b>	<b>10.53</b>

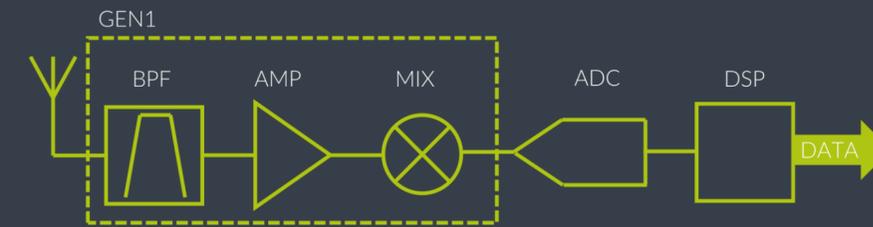


Technical specification	Multifractal's front-end (gen 1)
Tx power	>35 dBm
Tx antenna array	8x8 or more
EIRP	> 60 dBm
Range	<300 m
Gain	85-100 dB
Channel bandwidth	2 GHz (5 GHz potentially)
Rx elements	8x8 or more
Total Rx antenna gain	>25 dBi
NF	<5 dB
P1dB	> 20 dBm
IP3	> 25 dBm

1 - [https://www.itu.int/dms\\_pub/itu-r/opb/rep/R-REP-M.2376-2015-PDF-E.pdf](https://www.itu.int/dms_pub/itu-r/opb/rep/R-REP-M.2376-2015-PDF-E.pdf)  
 2 - [http://spathinc.com/spci/downloads/whitepapers/White\\_Paper\\_-\\_A\\_Straight\\_Path\\_Towards\\_5G.pdf](http://spathinc.com/spci/downloads/whitepapers/White_Paper_-_A_Straight_Path_Towards_5G.pdf)

# GENERATION 1 FRONT-END (telecoms)

High-level specifications

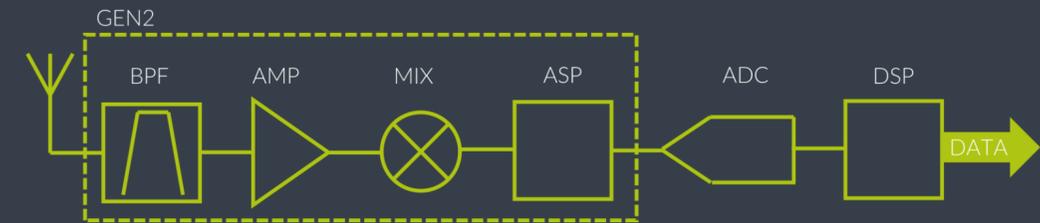


Parameter	Multifractal's gen 1 front-end	Siklu E-band front-end (EtherHaul 8010FX)	Our value add
Power consumption	< 2 W	50 W (including DSP)	10-20X power reduction
Cost	Tens of \$	~\$ 11k	>100X cost reduction
Channel bandwidth	5 GHz	2 GHz	SoC solution – fewer components, higher bandwidth, lower power
Throughput	10 Gbps full duplex	10 Gbps full duplex (FDD)	-
RF bands	71-76, 81-86 GHz	71-76, 81-86 GHz	-
System gain	80 – 98 dB	64 – 93 dB	-
Range	300 m	2.73 – 3.7 km	Small cell densification
Operating temperature	-45 to +85°C ++	-45 to +55°C	Single chip solution – better temperature performance / match
Dimensions	~ 10 by 10 cm (with MIMO array) – RF module (~5x5 cm)	~ 30 by 30 cm (single antenna – no MIMO)	Massive MIMO
Weight	< 100 g	~ 5 kg	Small, lightweight
NF	~5 dB	?	Relaxed requirements due to small cell dens.

Smaller range has benefits – our solution allows for this small cell dens. due to lower costs, power and size

# GENERATION 2 FRONT-END (telecoms)

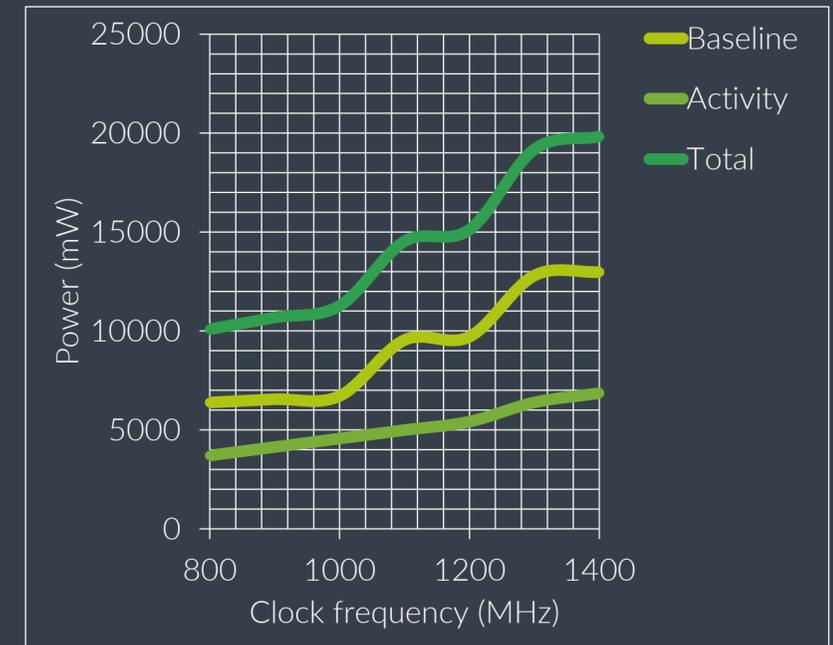
High-level specifications (ASP only – **cognitive radio** – other specs stay the same)



Existing solution do not scale well with bandwidth

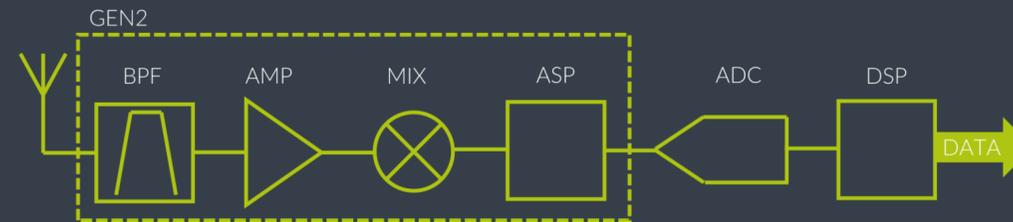
TI 66x (8 cores)

Parameter	Multifractal's IC	TI's AWR1243 / DSP 66x series or equivalent	Our value add
Power consumption	< 20 W (incl. DSP)	> 100 W (incl. DSP)	5-10X reduction
Cost	Hundreds of \$	Thousands \$	>100X reduction
Processing speed	< 50 ns per FFT	> 1 μs per FFT (1 core)	50X improvement (faster multiple object detection)
IF bandwidth (automotive radar)	1-4 GHz	5 MHz	100X faster (faster detection)
RF bandwidth (automotive radar)	4 – 8 GHz	4 GHz	2X larger → 2X resolution (4.5cm → 2.25 cm)
Complexity	Final system design = simple/no IMA!	Final system design = complex IMA	Supports mass production, lower production costs
Dynamic range	50 dB	~50 dB	-
ENOB	4	8	Relaxed ADC requirements
Equivalent n-points	70 (current technology with the aim to improve)	-	-
Power accuracy	±3 dB	~ 1 dB	-
Frequency accuracy	~ 100 Mhz	~ 100 MHz	-
Magnitude / phase information	Magnitude only	Both	Application dependent

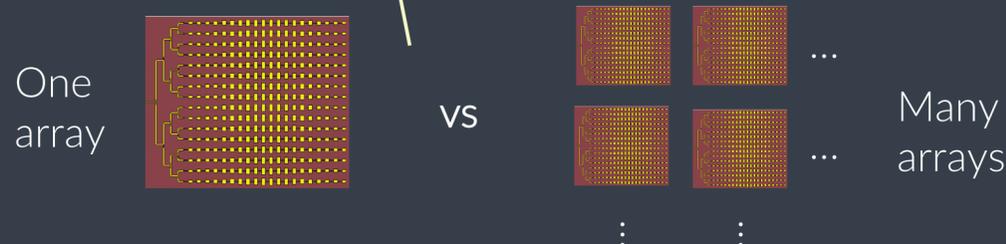
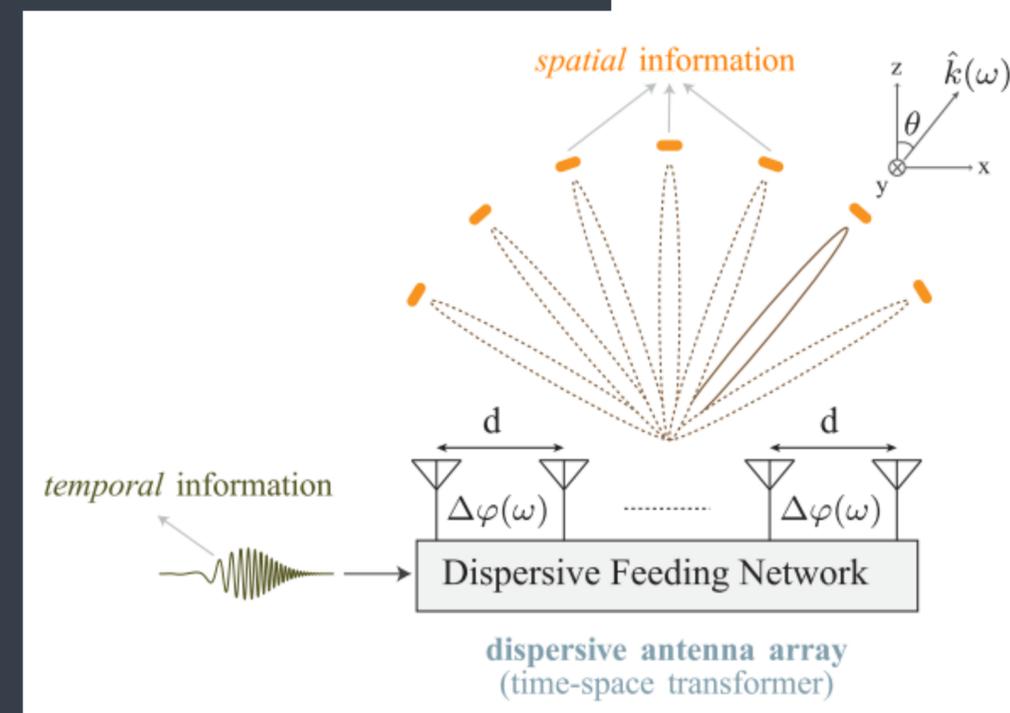
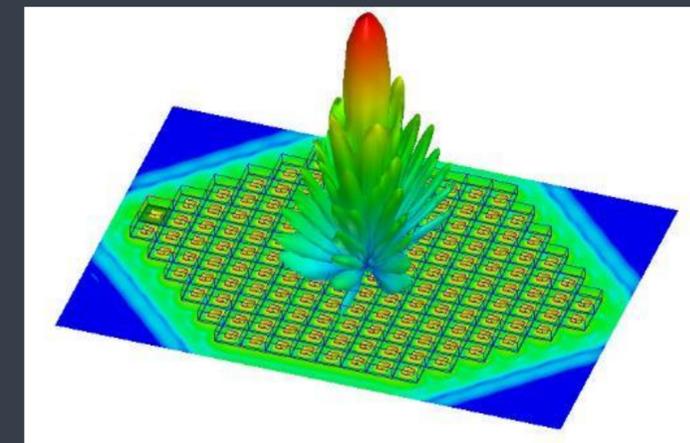
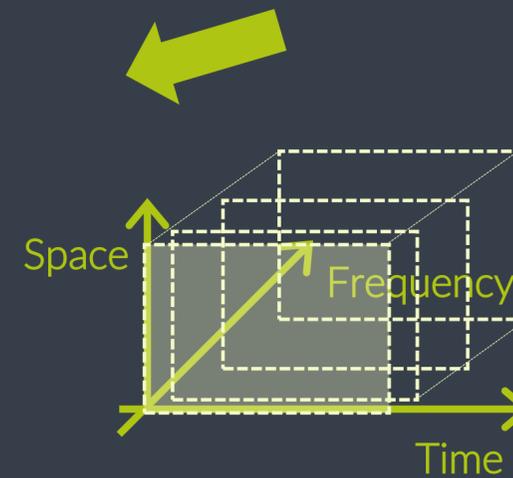


# GENERATION 2 FRONT-END (telecoms)

High-level specifications (ASP only – frequency beam steering – other specs stay the same)



Parameter	Multifractal's IC	TI's AWR1243 / DSP 66x series or equivalent	Our value add
Power consumption	< 20 W (incl. DSP)	> 100 W (incl. DSP)	5-10X reduction
Cost	Hundreds of \$	Thousands \$	10X reduction
Processing speed (tracking speed)	< 50 ns per operation	> 1 μs per operation (1 core)	50X improvement (faster steering)
Complexity	Final system design = simple/no IMA!	Final system design = complex IMA	Supports mass production, lower production costs
Dynamic range	50 dB	~50 dB	-
Bandwidth	> 8GHz	4 GHz is already a challenge	-
Channels per antenna (frequency mapped to angles)	> 30 (only one array! – one tile)	? (Unheard of) – many tiles / antenna arrays needed	More massive MIMO! Truly big data.
Frequency reconfigurability (lens effect)	8 GHz band → 100 MHz band	Unheard of	Frequency lensing



# APPENDIX - TECHNOLOGY OVERVIEW

# TECHNOLOGY OVERVIEW

UK Provisional Patent Application 1720870.3  
PCT to be filed in next few weeks

1. Fully tunable, active, enhanced, high Q-factor mm-wave resonators



Resonator is the building block of the BPF. Nobody in industry has integrated BPF on Silicon due to low  $Q_0$ -factors.

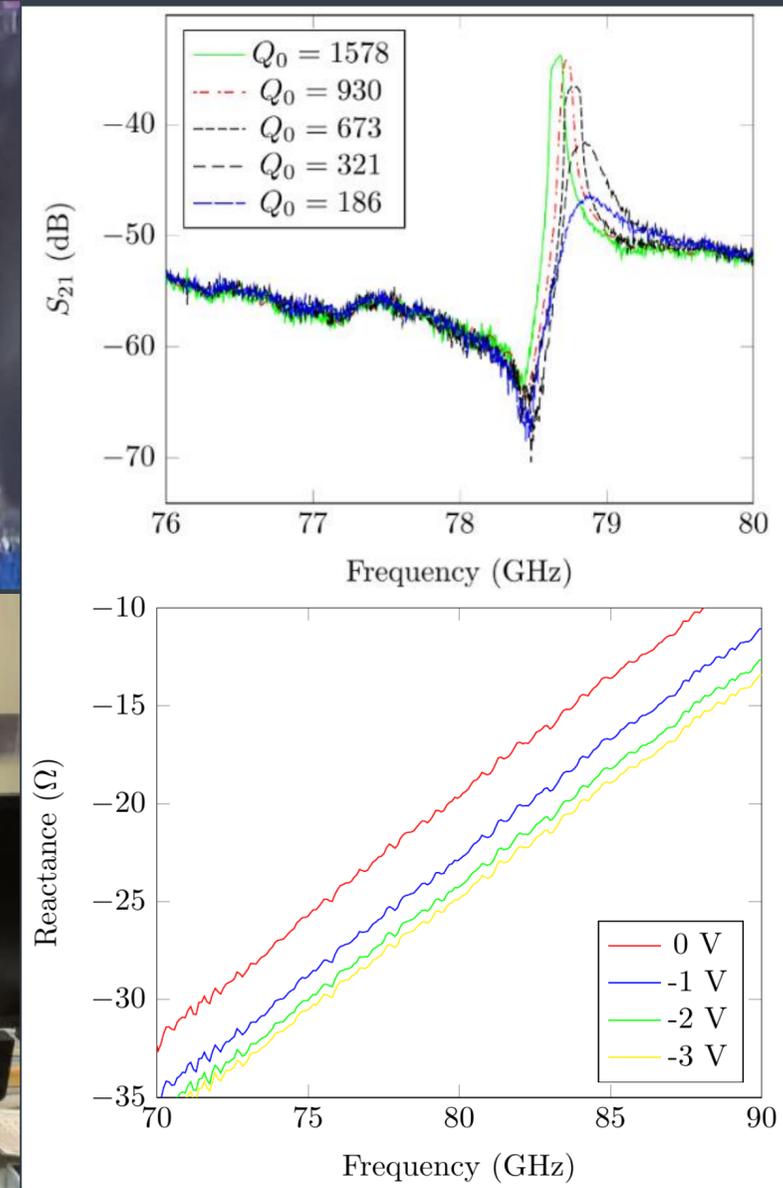
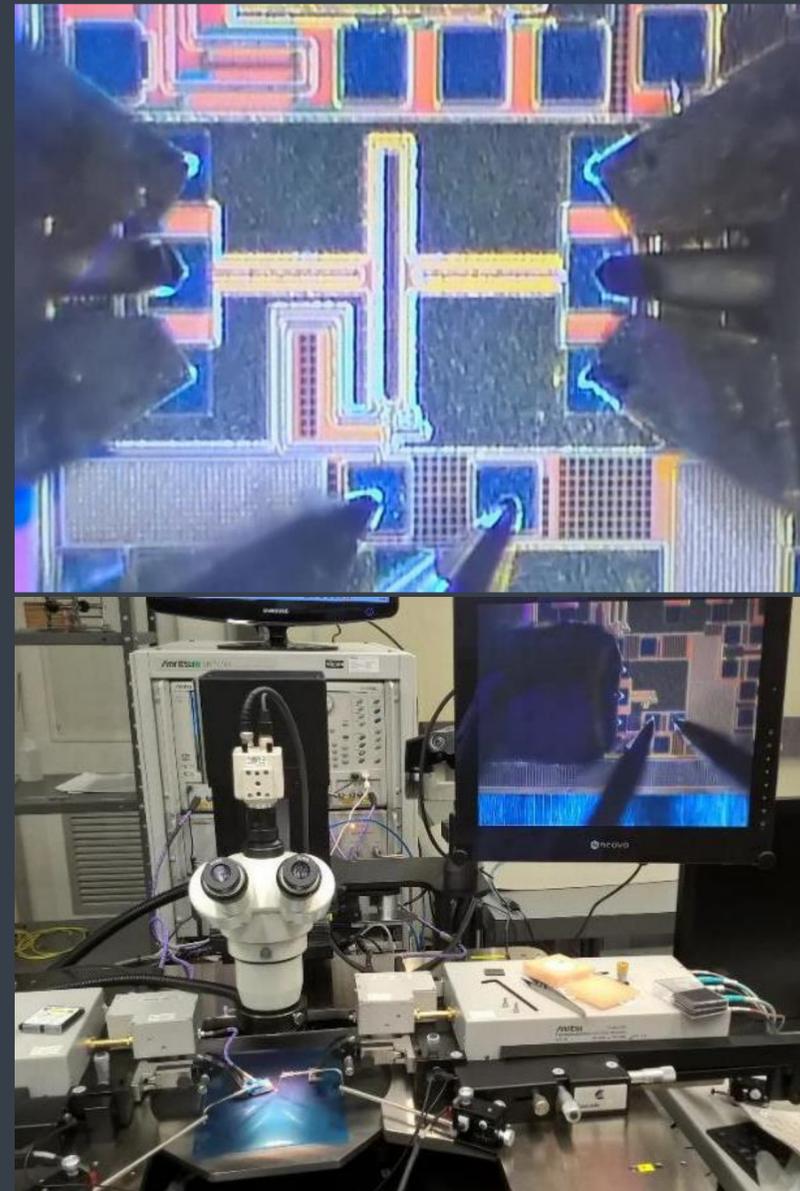
Silicon-proven in 130nm BiCMOS  
GF US 8HP with HBT ft/fMAX  
260/320 GHz

SOTA  $Q_0$  of  $\approx 10$ , Our  $Q_0$  of  $\approx 1000$

Can be scaled for other mmWave frequencies and processes (XXnm, CMOS, SOI, BiCMOS)

E-band (71-76 and 81-86 GHz)

Centre frequency and Q-factor tunable post-production with control voltages



First-ever on-chip mm-wave microstrip resonators with  $Q > 100$

# TECHNOLOGY OVERVIEW

UK Provisional Patent Application 1720870.3  
PCT to be filed in next few weeks

1. Fully tunable, active, enhanced, high Q-factor mm-wave resonators



$f_0$ (GHz)	FBW	Process	IL (dB)	Q-factor	Ref.
78	< 10 %	0.13 $\mu\text{m}$ SiGe BiCMOS	< 0.1	> 1500	This work
77	15.5 %	0.14 $\mu\text{m}$ SiGe BiCMOS	6.4	↑	[1]
77	11.7 %	0.13 $\mu\text{m}$ standard CMOS	3.9		[2]
77	28.6 %	0.18 $\mu\text{m}$ standard CMOS	3.8		[3]
70	25.7 %	0.18 $\mu\text{m}$ standard CMOS	3.6		[4]
65.0	3.23%	0.15 $\mu\text{m}$ GaAs	2.8	< 100	[6]
65.0	4.00%	0.15 $\mu\text{m}$ GaAs	3.0		[6]
22.7	7.39%	0.18 $\mu\text{m}$ CMOS	0.15		[7]
6.45	17.05%	2.00 $\mu\text{m}$ GaAs	0.25 gain		[8]

1. B. Dehlink, M. Engl, K. Aufinger, and H. Knapp, "Integrated Bandpass Filter at 77 GHz in SiGe Technology," IEEE Microw. Wirel. Components Lett., vol. 17, no. 5, pp. 346–348, May 2007.
2. Y.-M. Chen and S.-F. Chang, "A ultra-compact 77-GHz CMOS bandpass filter using grounded pedestal stepped-impedance stubs," 41st Eur. Microw. Conf., no. October, pp. 194–197, 2011.
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# TECHNOLOGY OVERVIEW

PCT filed – PCT/IB/2018/058738

57

## 2. Tunable active second-order all-pass network (CMOS)

Second-order all-pass network - building block of any ASP

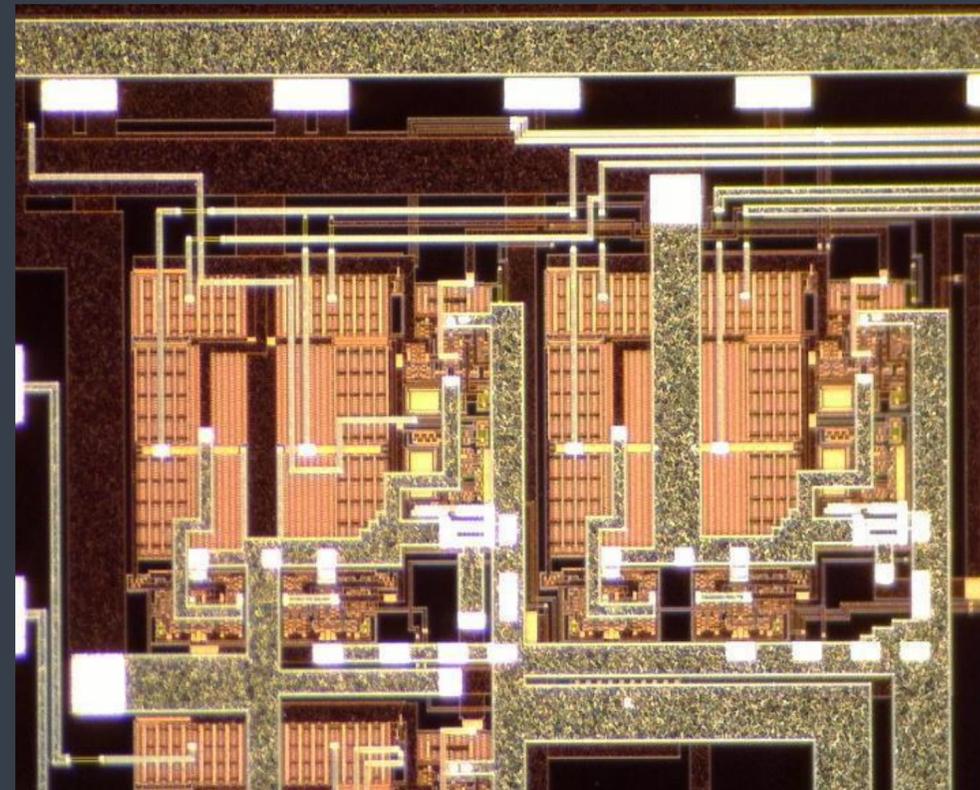
SOTA all-pass network - bulky soft-substrate passive microstrip

Multifractal - first-ever active on-chip second-order all-pass network with delay Q-value larger than 1

- Low insertion loss ripple ( $< 3.1$  dB)
- Bandwidth of 280 MHz in 0.35  $\mu\text{m}$  CMOS
- 0.0625 mm<sup>2</sup> real-estate
- Reduced sensitivity to process tolerances

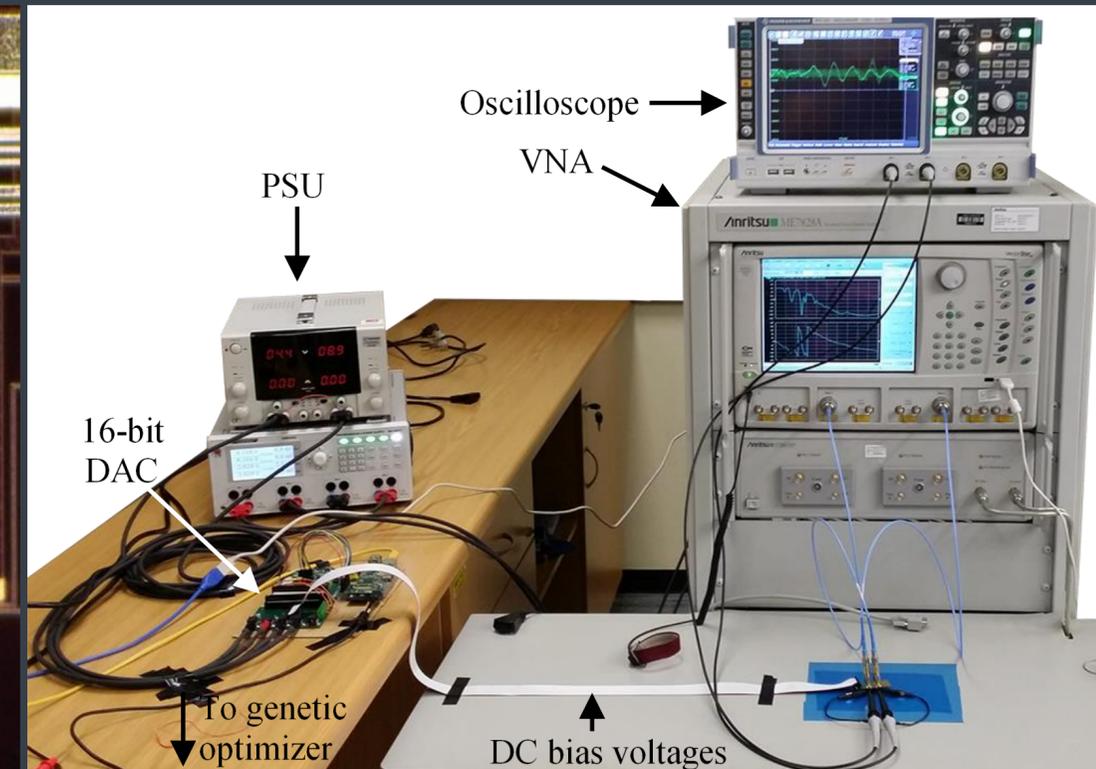
Prototyped in 0.35  $\mu\text{m}$  CMOS and measured

Manufactured using:



Second-order all-pass network – micrograph

100 microns



Second-order all-pass network – measurement setup

# TECHNOLOGY OVERVIEW

## 2. Tunable active second-order all-pass network (CMOS)

Ref.	ORDER	$Q_D$	$f_0$ (GHz)	-3dB Bandwidth h (GHz)	Technology	# of L	Size (mm <sup>2</sup> )	Power (mW)	Magnitude variation (dB)
This work	2 <sup>nd</sup>	1.15	0.07 3	0.280	0.35 $\mu$ m CMOS	0	0.0625	15 (excl. DAC)	3.1
[1]	2 <sup>nd</sup>	0.19 (0.59) <sup>***</sup>	3	4	0.25 $\mu$ m CMOS	0	0.085	< 95	1.5 (> 25)
[2]	2 <sup>nd</sup>	0.04 (0.52)	7	13	0.13 $\mu$ m CMOS	1	0.0627	18.5	0.5 (> 13)
[3]	2 <sup>nd</sup>	0.098	7	16.5	0.09 $\mu$ m CMOS	0	-	< 27	< 1
[4]	2 <sup>nd</sup>	0.049 (0.61)	6.3	12	0.13 $\mu$ m CMOS	1	-	16.5	~ 1.5 (> 10)
[5]	2 <sup>nd</sup>	0.047	6	7.5	SiGe BiCMOS HBT ( $f_T = 95$ GHz)	1	0.49*	121	~ 1
[6]	2 <sup>nd</sup> ( $f_0 = 0$ ) <sup>**</sup>	0	0	12.2	0.16 $\mu$ m CMOS	0	0.15	90	1.4
[7]	0 <sup>th</sup> ( $f_0 = 0$ ) <sup>**</sup>	0	0	10	SiGeRF HBT ( $f_T = 80$ GHz)	2	0.4197	38.8	2 – 2.5
[8]	2 <sup>nd</sup> ( $f_0 = 0$ ) <sup>**</sup>	0	0	4.38	0.18 $\mu$ m CMOS	0	0.0512	7.88	-
[9]	2 <sup>nd</sup> ( $f_0 = 0$ ) <sup>**</sup>	0	0	> 3	0.13 $\mu$ m CMOS	0	0.29	112	~ 0.75

\* Including pads, \*\* constant delay with frequency, \*\*\* values in brackets are computed over the entire bandwidth with the associated magnitude variation also shown in brackets.

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5. Hamouda, M., Fischer, G., Weigel, R., Ussmueller, T.: 'A compact analog active time delay line using SiGe BiCMOS technology', in '2013 IEEE International Symposium on Circuits and Systems' (2013), pp. 1055–1058
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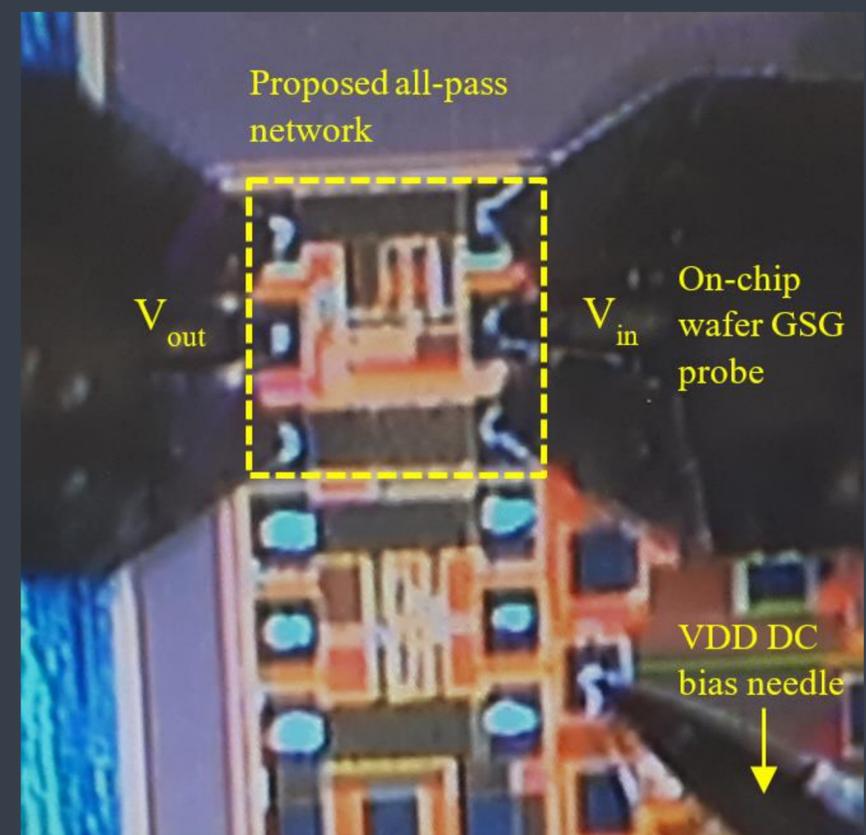
# TECHNOLOGY OVERVIEW

Know-how

## 3. Mm-wave active second-order all-pass network (BiCMOS)

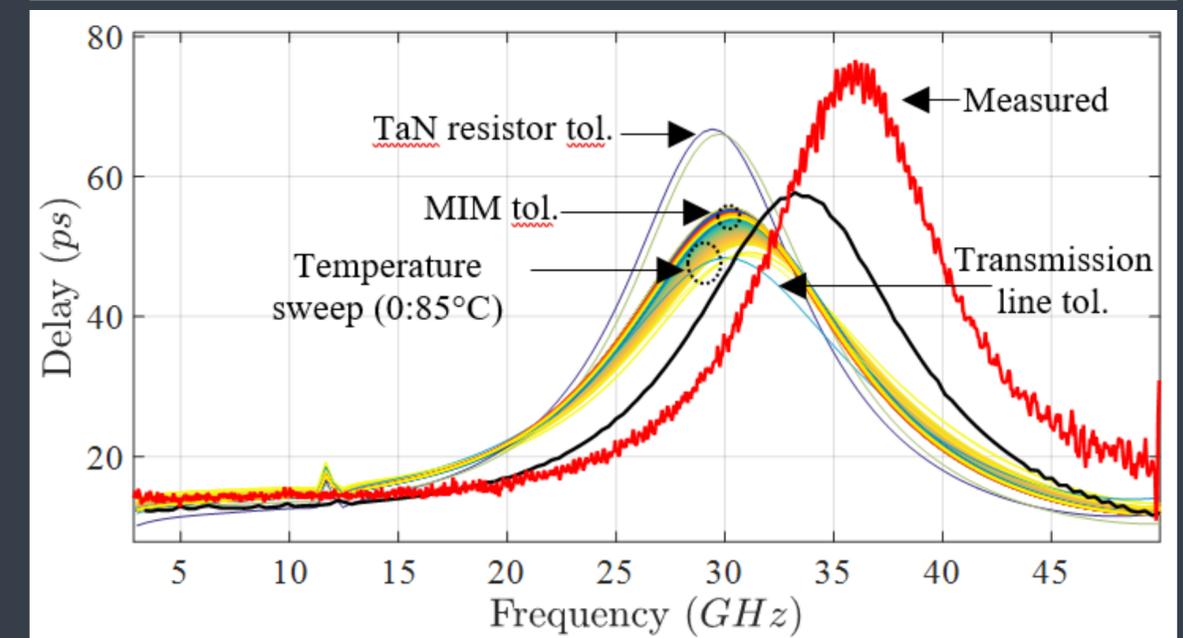
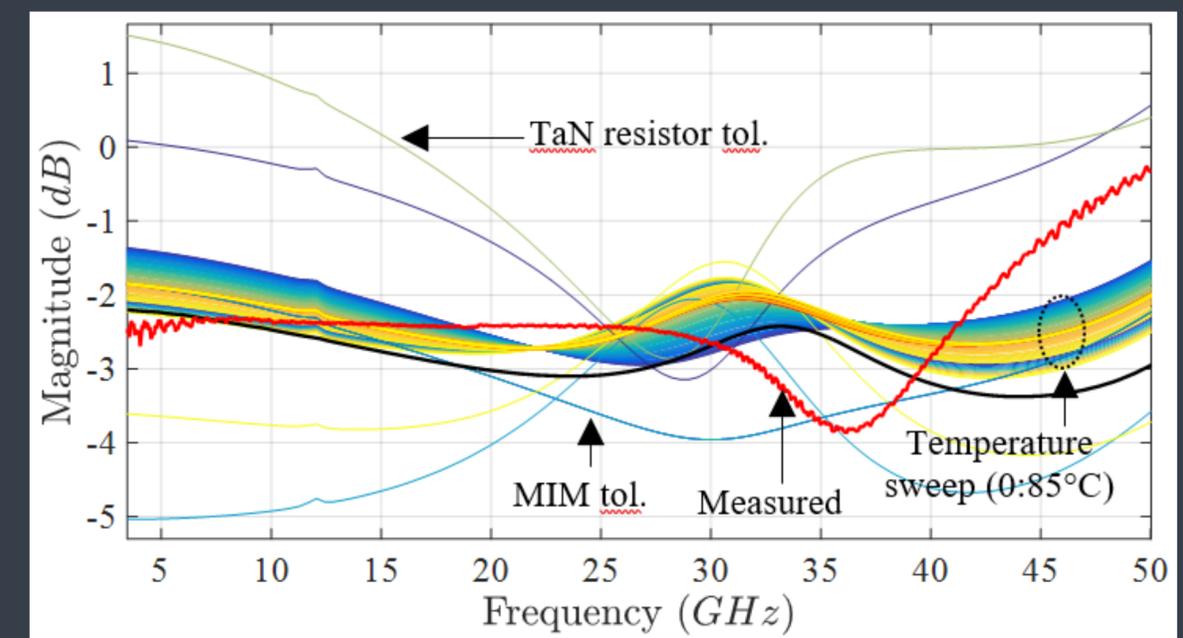
- First mm-wave second-order all-pass network: 10 GHz linear group delay bandwidth
- Prototype - 130 nm BiCMOS
- Power - 20 mW  
Size - 0.09 mm<sup>2</sup>
- Average output noise of 0.69 nV/√Hz
- Prototyped, measurements pending

Manufactured using: 



Mm-wave bandwidth CCII – micrograph

150 microns



Mm-wave bandwidth CCII – simulated results

# TECHNOLOGY OVERVIEW

## 3. Mm-wave active second-order all-pass network (BiCMOS)

	$Q_D$	$f_0$ (GHz)	-3dB (GHz)	Technology	Size (mm <sup>2</sup> )	Power (mW)	$\Delta  T $ (dB)**
[*]	3.6	36	40	0.13 $\mu$ m SiGe	0.0625	9.3	1.4
[4]	0 <sup>^</sup>	0	12.2	0.16 $\mu$ m CMOS	0.07	90	~ 1.4
[5]	0 <sup>^</sup>	0	4.38	0.18 $\mu$ m CMOS	0.0512	7.88	-
[7]	0.19	3	4	0.25 $\mu$ m CMOS	0.085	< 95	~ 1.5
[8]	0.04	7	13	0.13 $\mu$ m CMOS	0.0627	18.5	~ 0.5
[9]	0.098	7	16.5	0.09 $\mu$ m CMOS	-	< 27	< 1
[10]	0.049	6.3	12	0.13 $\mu$ m CMOS	-	16.5	~ 1.5
[11]	0.047	6	7.5	0.25 $\mu$ m SiGe	0.49 <sup>#</sup>	121	~ 1

\*This work. <sup>^</sup>Cascaded two first-order sections (no complex pole/zero). <sup>#</sup>Including pads. <sup>\*\*</sup>T represents either a power or voltage transfer function.

1. S. K. Garakoui, E. A. Klumperink, B. Nauta, and F. E. van Vliet, "Compact cascadable gm-C all-pass true time delay cell with reduced delay variation over frequency," IEEE Journal of Solid-State Circuits, vol. 50, no. 3, pp. 693–703, 2015.
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3. X. Lin, J. Liu, H. Lee, and H. Liu, "A 2.5- to 3.5-Gb/s adaptive FIR equalizer with continuous-time wide-bandwidth delay line in 0.25- $\mu$ m CMOS," IEEE Journal of Solid-State Circuits, vol. 41, no. 8, pp. 1908–1918, 2006.
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5. M. Maeng et al., "0.18- $\mu$ m CMOS equalization techniques for 10-Gb/s fiber optical communication links," IEEE Transactions on Microwave Theory and Techniques, vol. 53, no. 11, pp. 3509–3519, 2005.
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7. M. Hamouda, G. Fischer, R. Weigel, and T. Ussmueller, "A compact analog active time delay line using SiGe BiCMOS technology," in 2013 IEEE International Symposium on Circuits and Systems, 2013, pp. 1055–1058.

# TECHNOLOGY OVERVIEW

PCT filed – PCT/IB/2018/058805

Manufactured using:  


## 4. High-precision CMOS CCII with stability and peaking control

A CCII is a versatile analogue building block (of for e.g. all-pass networks)

Large bandwidths (800 MHz – 350 nm CMOS)

High accuracy (feedback mechanism) - voltage and current following to within 0.5 %

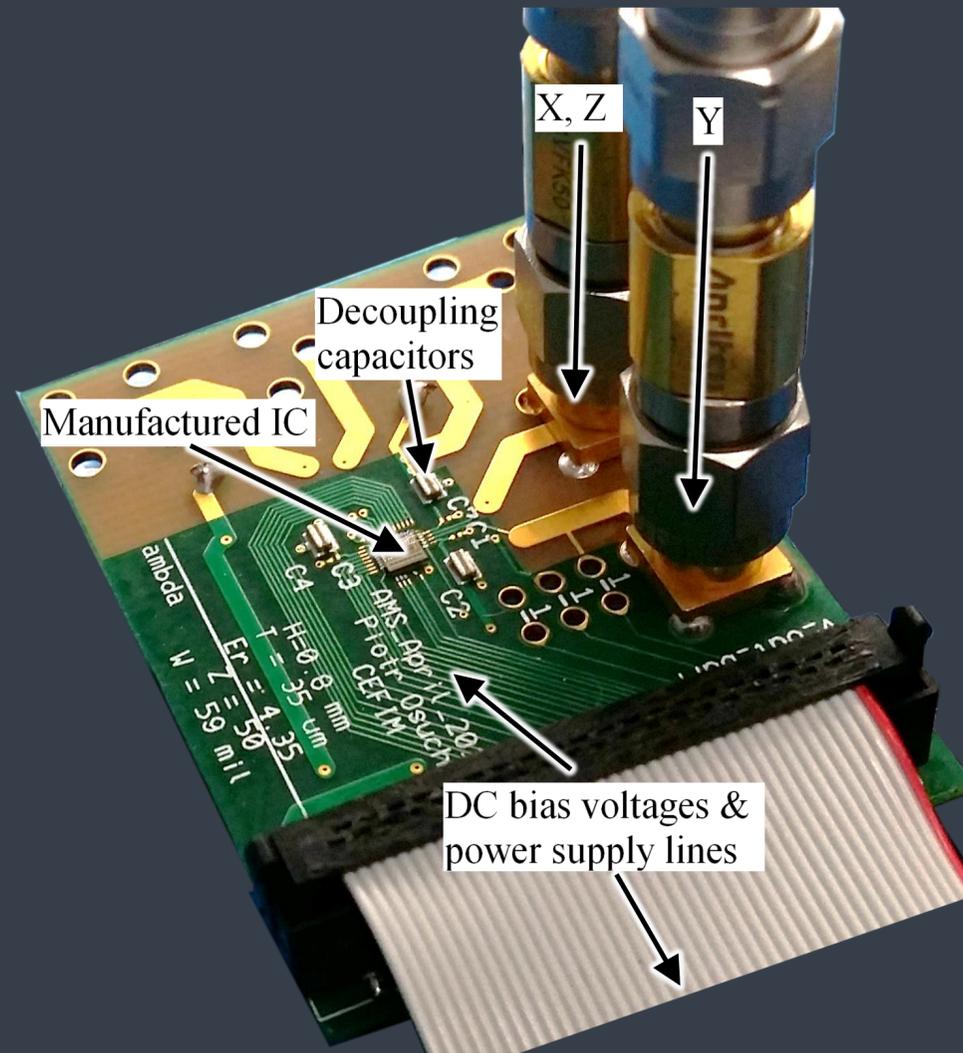
Stability of the feedback loop (post-production tunable phase margin)

Post-production peaking control (reduce ripple) to account for process tolerances

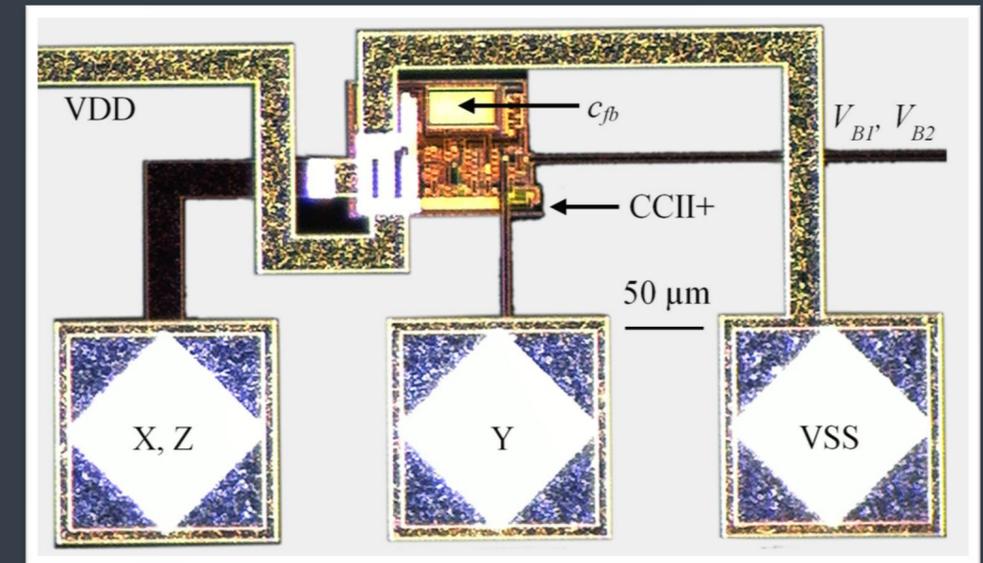
Prototyped and measured:

Power – 5 mW

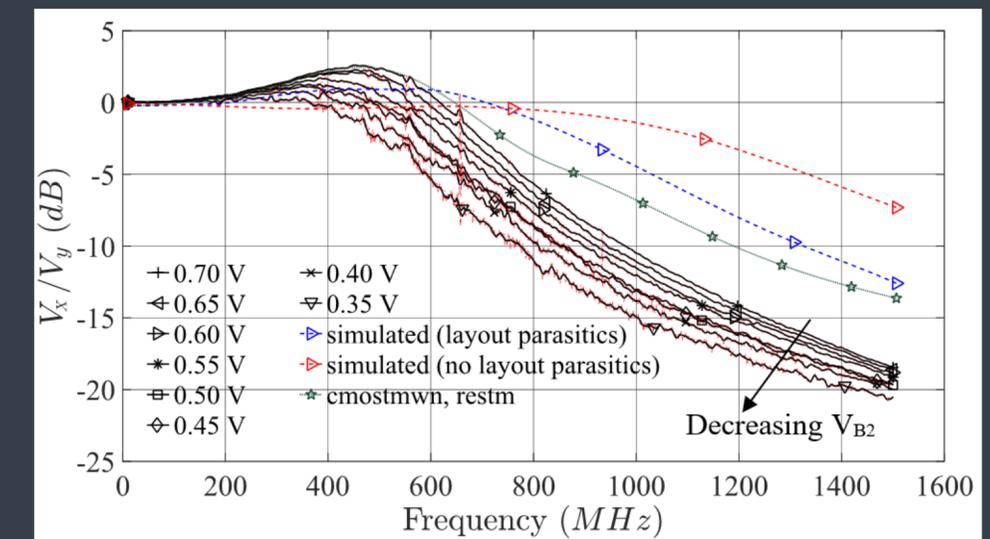
Size – 0.023 mm<sup>2</sup>



CCII+ – measurement setup



CCII+ – micrograph



CCII+ – measurement

# TECHNOLOGY OVERVIEW

PCT filed – PCT/IB/2018/058805

62

Manufactured using:



## 4. High-precision CMOS CCII with stability and peaking control

Ref.	VOLTAGE GAIN (B)	Current gain ( $\alpha$ )	$R_x$ ( $\Omega$ )	$R_y$ (k $\Omega$ )	$R_z$ (k $\Omega$ )	-3dB Bandwidth (MHz)	Technology	Measured Results
This work	1.0115	1.0115	< 5	45	20	500	0.35 $\mu$ m CMOS	Yes
[1]	-	-	100	-	-	~1	off-chip	Yes
[2]	0.9886	-	0.3	-	-	20	1.2 $\mu$ m CMOS	No
[3]	0.99	0.99	2.3	-	-	10	0.6 $\mu$ m CMOS	No
[4]	1	1	11.4	-	7200	16	0.35 $\mu$ m CMOS	No
[5]	-	-	~50	-	-	700	1.2 $\mu$ m CMOS	No
[6]	0.9999	0.9999	0.06	-	-	2.16	0.5 $\mu$ m CMOS	No
[7]	0.96	0.976	18	25	35	2600	0.35 $\mu$ m CMOS	No
[8]	0.995	-	1.15	3900	2800	~50	0.35 $\mu$ m CMOS	No
[9]	1.0000	0.9999	3.7	-	-	~400	0.5 $\mu$ m CMOS	No
[10]	1.0005	1.0015	0.003	-	-	~250	1.2 $\mu$ m CMOS	No

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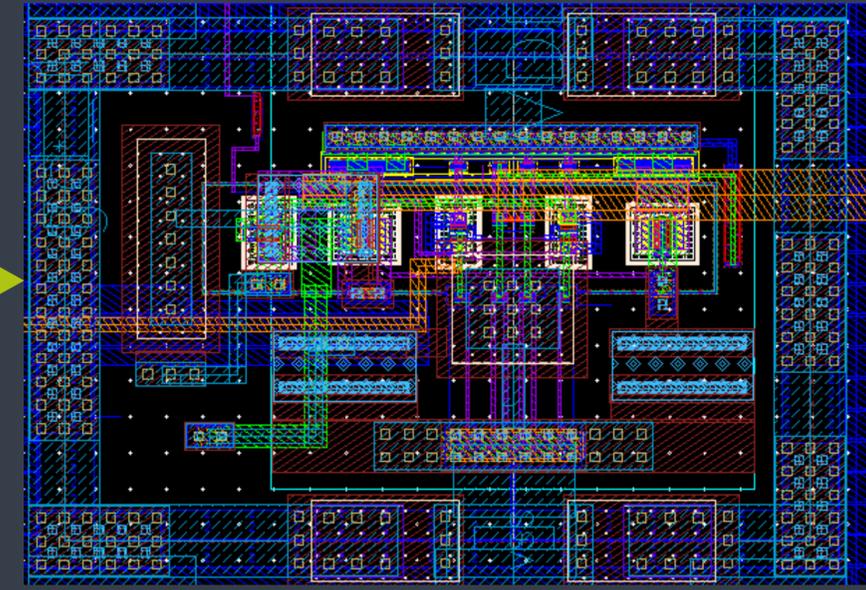
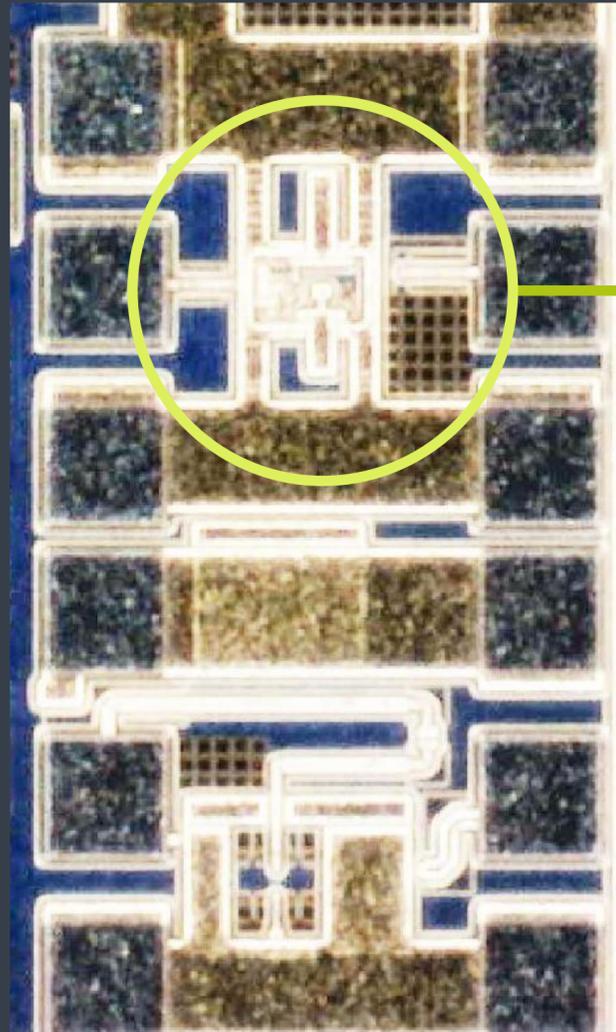
# TECHNOLOGY OVERVIEW

Know-how, PCT to be filed (potentially)

## 5. Mm-wave bandwidth CCII with peaking reduction (BiCMOS)

Manufactured using:  GLOBAL FOUNDRIES

- Mm-wave bandwidths (27 GHz) - first time ever.
- Feedback mechanism to improve precision (to within 1 %)
- Peaking reduction (reduce passband ripple)
- Prototyped and measured - post-processing pending



150 microns

First-ever mm-wave bandwidth CCII

# TECHNOLOGY OVERVIEW

Know-how

64

## 6. Narrowband coupled resonator bandpass filters

First narrowband on-chip mmWave BPF (can be scaled to various topologies)

Fractional bandwidths of 0.5%  
Filters as narrow as 500 MHz

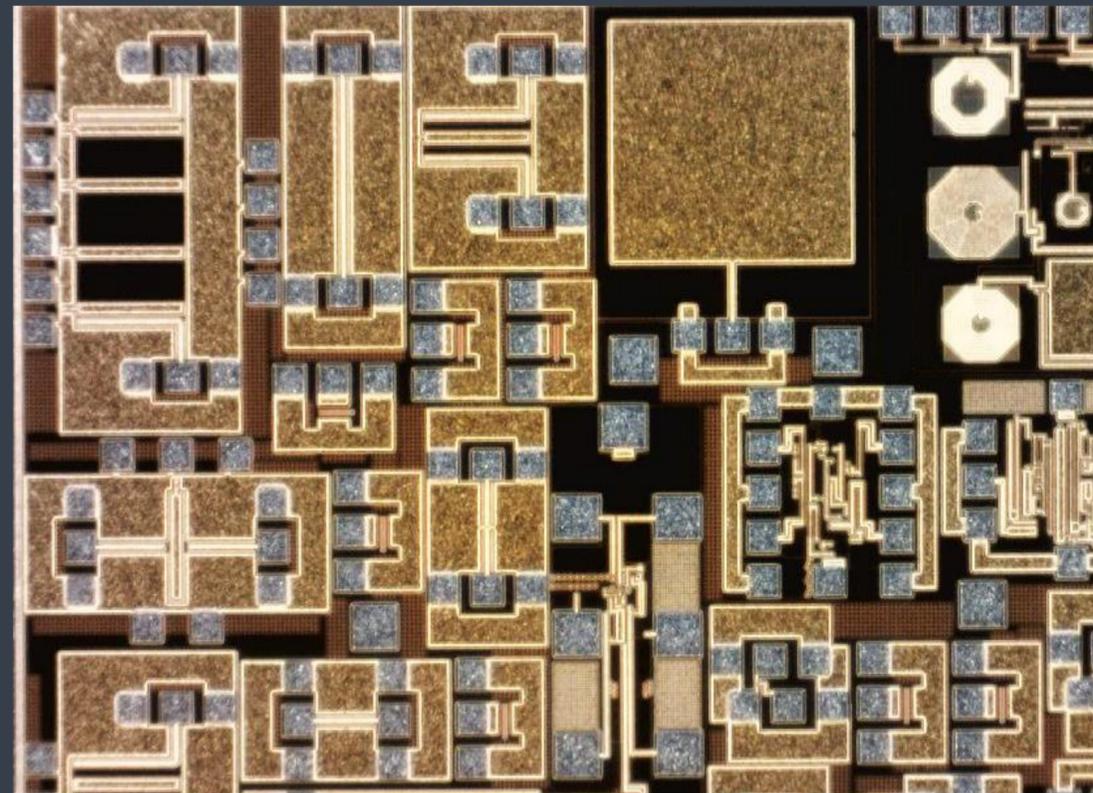
Applicable to E-Band 71-76 and 81-86 GHz

Resonator  $Q_0$  enhanced from 10 to 1000.

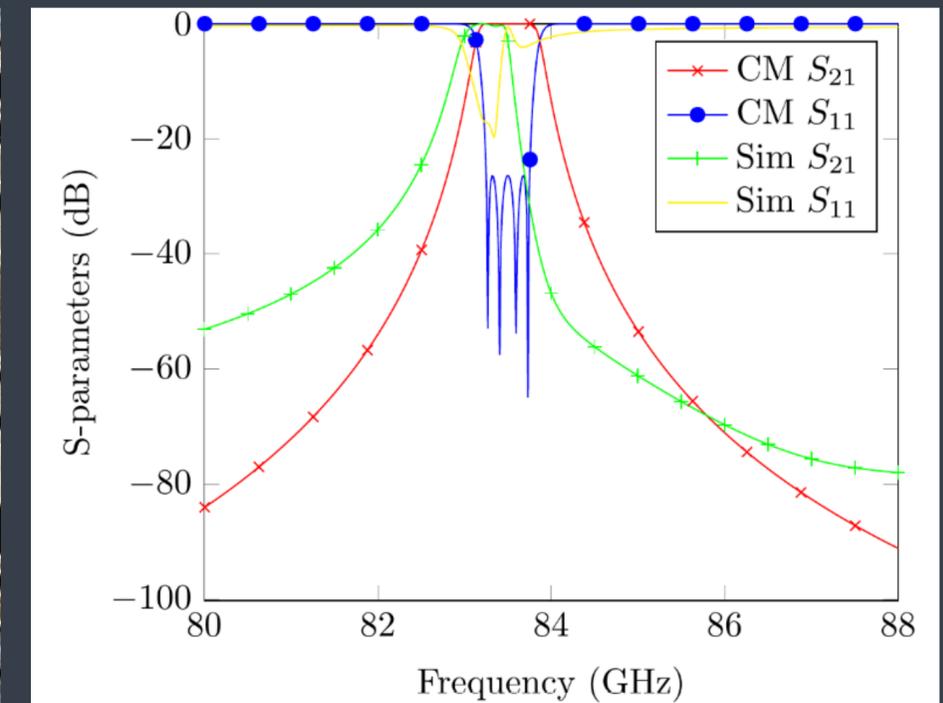
Opportunities for extension to a tunable BPF and/or low-noise filtering amplifier

Second prototype pending - pending funding

Manufactured using:  GLOBAL FOUNDRIES



Simulation results of the tunable, high-Q mm-wave resonators



300 microns

# TECHNOLOGY OVERVIEW

Know-how

65

## 7. Mm-wave LNA

Manufactured using:  GLOBAL FOUNDRIES

An LNA is a key component of any transceiver

56-92 GHz operating range

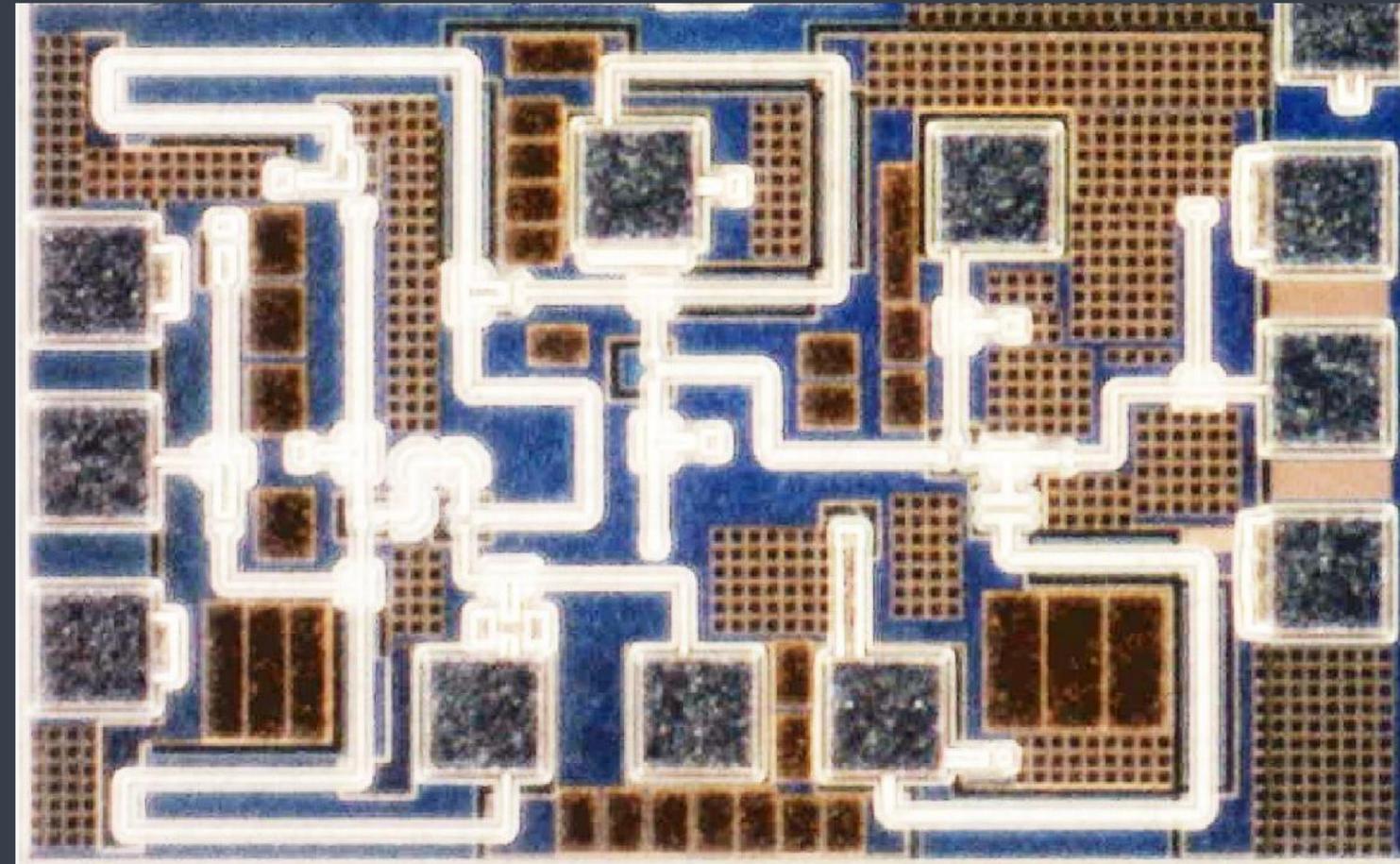
15 GHz bandwidth

Gain of > 13 dB

NF < 8 dB

Complements Multifractal's technology portfolio enabling a future climb in the value chain

Noise measurements pending - pending funding



Mm-wave LNA

150 microns